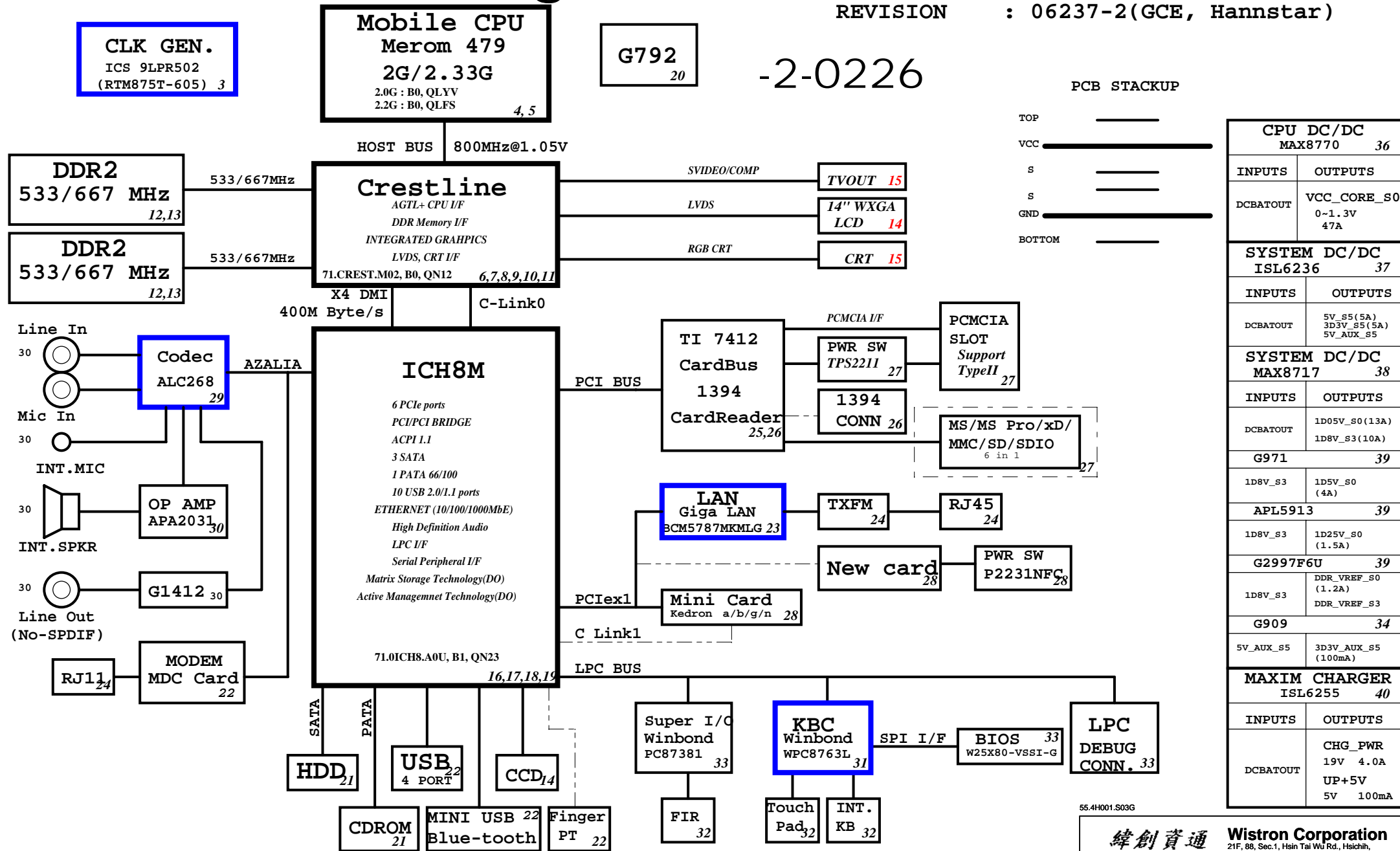


# Biwa Block Diagram

Project code: 91.4H001.001  
 PCB P/N : 55.4H001.XXX  
 REVISION : 06237-2(GCE, Hannstar)



55.4H001.S03G

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **BLOCK DIAGRAM**

Size A3 Document Number **Biwa** Rev **-2**

Date: Thursday, March 01, 2007 Sheet 1 of 42

# ICH8M Functional Strap Definitions

ICH8-M EDS 21762 2.0V1 page 16

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIe Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low. When TP3 not pulled low at rising edge of PWROK, sets bit1 of RPC.PC(Config Registers: offset 224h)
HDA_SYNC	PCIe config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#	PCIe config2 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPIO20	Reserved	This signal should not be pulled high.
GNT1#/ GPIO51	ESI Strap (Server Only) Rising Edge of PWROK	ESI compatible mode is for server platforms only. This signal should not be pulled low for desktop and mobile.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#/ SPI_CS1#	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
INTVRMEN	Integrated VccSus1_05, VccSus1_5 and VccCL1_5 VRM Enable/Disable. Always sampled.	Enables integrated VccSus1_05, VccSus1_5 and VccCL1_5 VRM's when sampled high
LAN100_SLP	Integrated VccLAN1_05 and VccCL1_05 VRM Enable/Disable. Always sampled.	Enables integrated VccLAN1_05 and VccCL1_05 VRM's when sampled high
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH8 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPIO33/ HDA_DOCK _EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	This signal has a weak internal pull-up. Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be used in manufacturing environments.

# ICH8M IDE Integrated Series Termination Resistors

DD[15:0], DIOW#, DIOR#, DREQ, DDACK#, IORDY, DA[2:0], DCS1#, DCS3#, IDEIRQ	approximately 33 ohm
--	----------------------

# PCI Routing

page 17

	IDSEL	INT	REQ	GNT
TI7412	AD22	G:CARDBUS B:1394 F:Flash Media G:SD Host	0	0

# USB Table

USB	
Pair	Device
0	USB1
1	USB2
2	USB3
3	USB4
4	MINIC1
5	BT
6	CCD
7	Finger
8	NEW
9	NC

# PCIe Routing

LANE1	LAN BCM5787M
LANE2	MiniCard WLAN
LANE3	NewCard WLAN

# ICH8M Integrated Pull-up and Pull-down Resistors

ICH8-M EDS 21762 2.0V1

SIGNAL	Resistor Type/Value
HDA_BIT_CLK	PULL-DOWN 20K
HDA_RST#	NONE
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GNT[3:0]	PULL-UP 20K
GPIO[20]	PULL-DOWN 20K (?)
LDA[3:0]#/FHW[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 10K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPIO23	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#	PULL-UP 20K
SPI_CLK	PULL-UP 20K
SPI_MOSI	PULL-UP 20K
SPI_MISO	PULL-UP 20K
TACH_[3:0]	PULL-UP 20K (?)
SPKR	PULL-DOWN 20K
TP[3]	PULL-UP 20K
USB[9:0][P,N]	PULL-DOWN 15K
CL_RST#	PULL-UP 13K

# Crestline Strapping Signals and Configuration

Crestline EDS 20954 1.0 page 7

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	001 = FSB533 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG[8:6]	Reserved	
	Low Power PCI Express	0 = Normal mode 1 = Low Power mode (Default)
CFG9	PCI Express Graphics Lane Reversal	0 = Reverse Lanes,15->0,14->1 ect.. 1 = Normal operation(Default):Lane Numbered in order
CFG[11:10]	Reserved	
CFG[13:12]	XOR/ALL Z test straps	00 = Reserved 01 = XOR mode enabled 10 = All Z mode enabled 11 = Normal Operation (Default)
CFG[15:14]	Reserved	
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG[18:17]	Reserved	
CFG19	DMI Lane Reversal	0 = Normal operation (Default):lane Numbered in order 1 =Reverse Lane,4->0,3->1 ect...
CFG20	SDVO/PCIE Concurrent	0 = Only SDVO or PCIE x1 is operational (Default) 1 =SDVO and PCIE X1 are operating simultaneously via the PEG port
SDVOCRTL_DATA	SDVO Present	0 = No SDVO Card present (Default) 1 = SDVO Card present

NOTE: All strap signals are sampled with respect to the leading edge of the Crestline GMCH PWROK in signal.

# History

- 2007/02/16  
 1. Page 33: Add SIO 87381 for FIR Issue.  
 2. Page 31, change KBC from 8768L to 8763L.  
 3. Page 33, del U33(LPC golden Finger).  
 4. Page 24/32, change ERC1/ERC2 due to 77.61021.02L is Obsoleted Part !  
 5. Page 37, del TC22/TC19.  
 6. Page 38, del TC1/TC4.

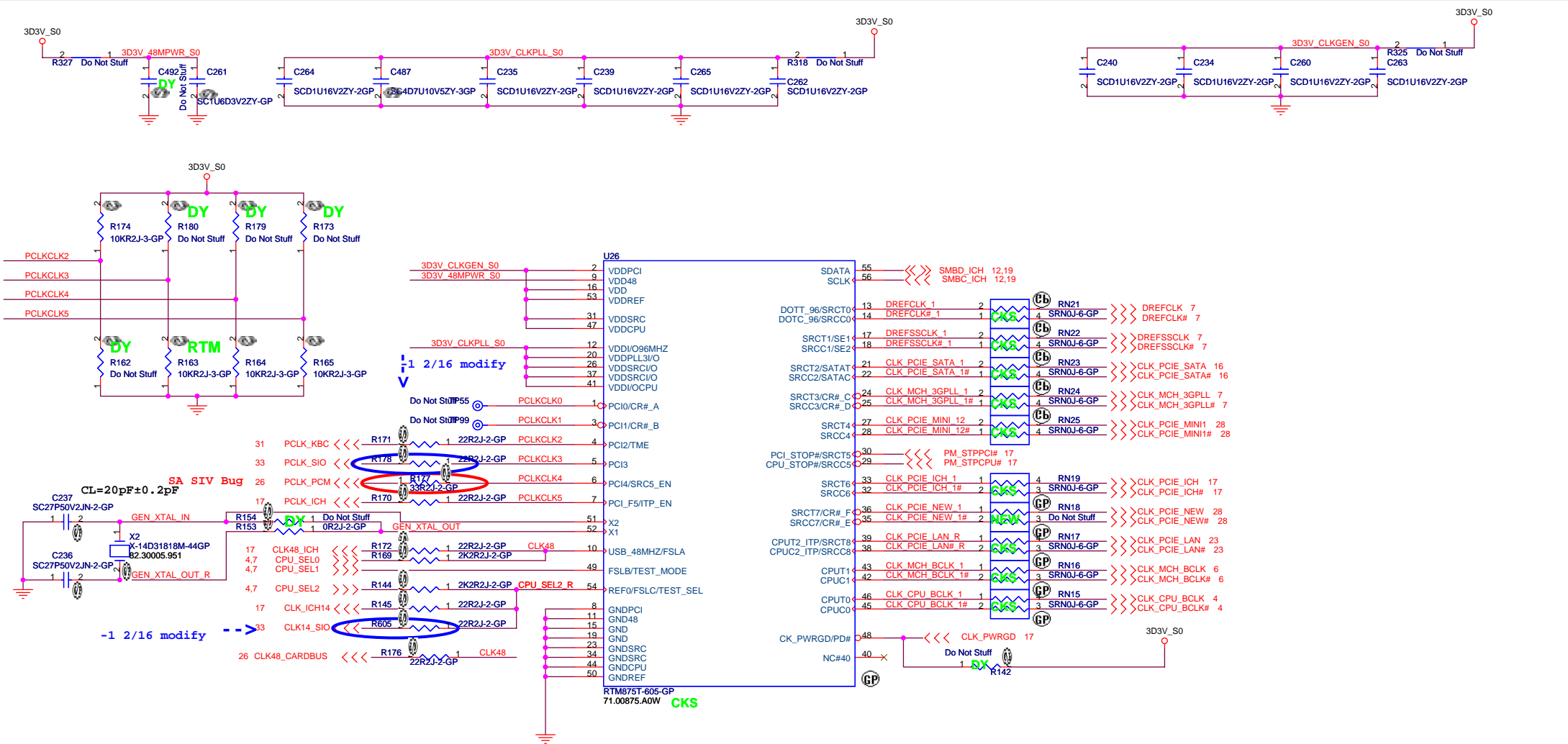
- 2007/02/09  
 1. Page 14:Modify "Q14" "BTBTN1" "WLBTN1" symbol.  
 2. Page 36, 37, 38: Replace 0ohm with 0ohm pad.

- 2007/02/08a  
 1. Page 14:Modify R428 to "FRONT\_PWRLED#\_1" and RN58 pin7 to "STBY\_LED#\_2" due to LED brightness issue.  
 2. Page 38:Replace "TC26" with "77.C1561.01L".

- 2007/02/08  
 1. Page 10:Replace "R244" with "0603-PAD".  
 2. Page 36:Replace open power gap with close power gap.  
 3. Page 38:Add capacitor "TC26" for acoustic noise

55.4H001.S03G

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Reference</b>			
Title	Document Number		
Size A3	<b>Biwa</b>		Rev -2
Date: Thursday, March 01, 2007	Sheet 2	of	42



ICS9LPR502HGLFT-GP setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1 = CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1 = CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1 = CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1 = CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI4/SRC5_EN	0 = Pin29 as CPU_STOP#, pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI_F5/ITP_EN	0 = SRCB/SRC# 1 = ITP/ITP#

RTM875T-605 setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1 = CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1 = CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1 = CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1 = CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI3/SRC-5_EN	0 = Pin29 as CPU_STOP#, pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI4/27M_SEL	0 = Pin17 as SRC-1, Pin18 as SRC-1#, Pin13 as DOT96, Pin14 as DOT96# 1 = Pin17 as 27MHz, Pin 18 as 27MHz_SS, Pin13 as SRC-0, Pin14 as SRC-0#
PCI_F5/ITP_EN	0 = SRCB/SRC# 1 = ITP/ITP#

SEL2	SEL1	SEL0	CPU	FSB
FSC	FSB	FSA		
1	0	1	100M	X
0	0	1	133M	X
0	1	1	166M	667M
0	1	0	200M	800M

55.4H001.S03G

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Clock Generator**

Size: Document Number **Biwa** Rev: **-2**

Date: Thursday, March 01, 2007 Sheet 3 of 42

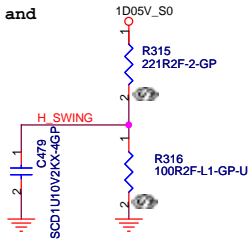
hexinf@topmail.com  
GRAITS - FOR FREE





H\_SWING routing Trace width and Spacing use 10 / 20 mil

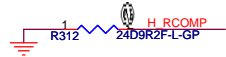
H\_SWING Resistors and Capacitors close MCH 500 mil ( MAX )



H\_SCOMP and H\_SCOMP# Resistors and Capacitors close MCH 500 mil ( MAX )

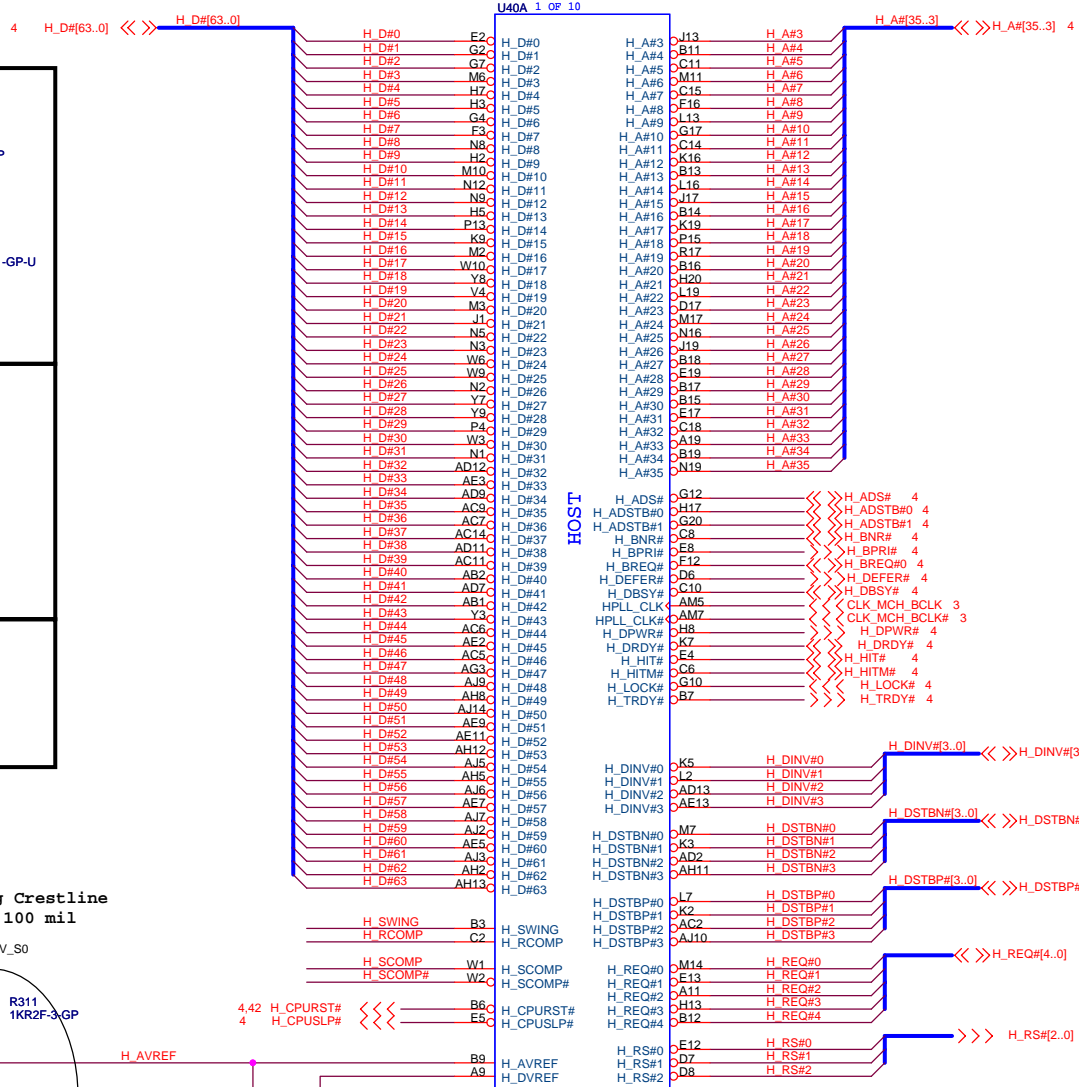
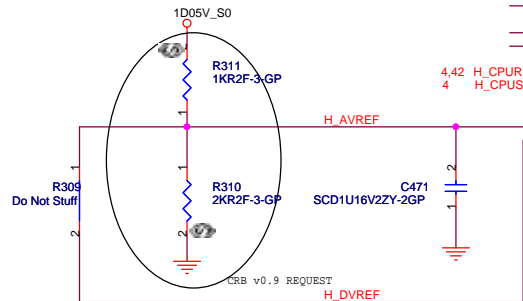


H\_RCOMP routing Trace width and Spacing use 10 / 20 mil



Place them near to the chip ( < 0.5" )

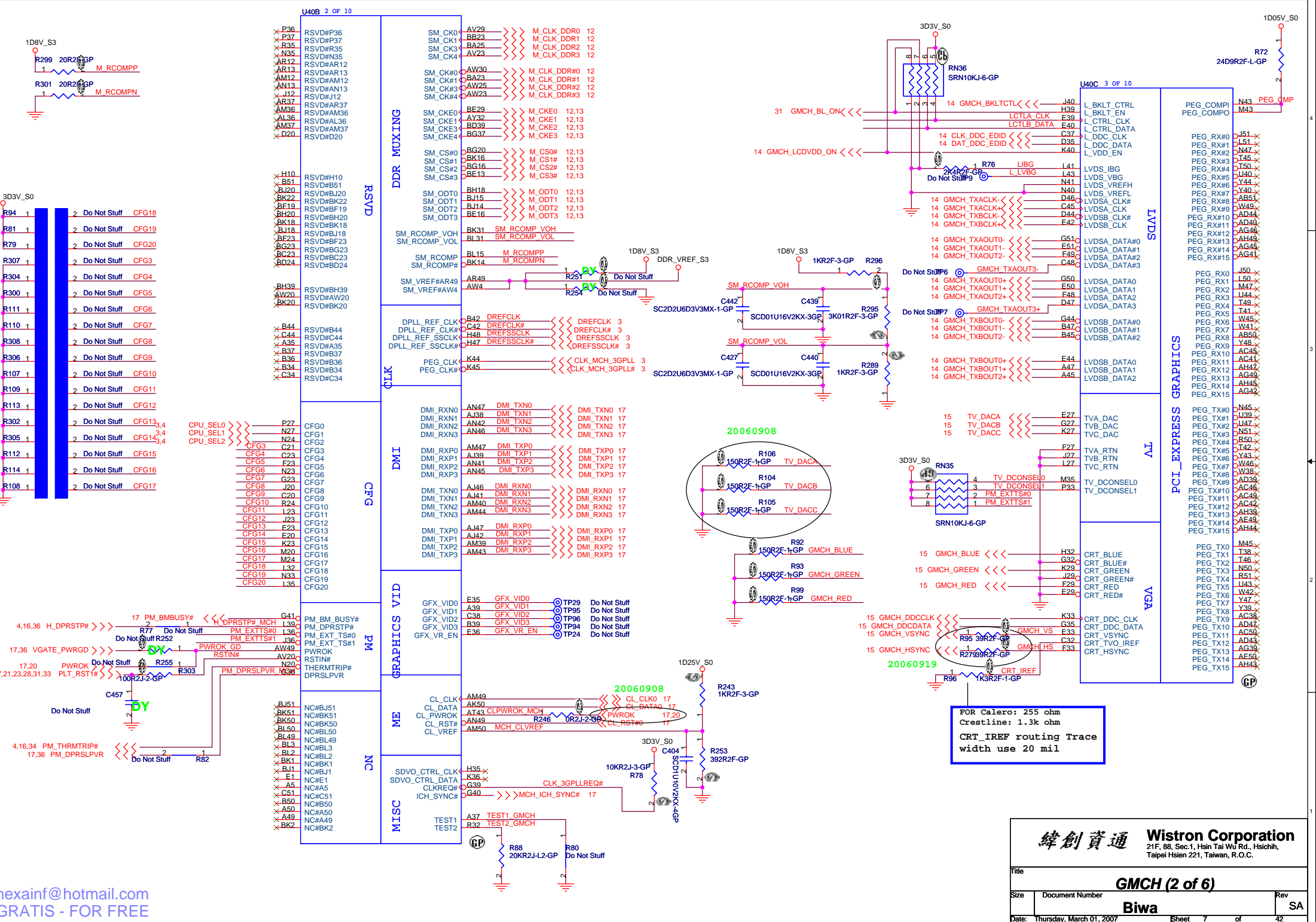
H\_REF Decoupling Crestline close Crestline 100 mil



55.4H001.S03G

緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		GMCH (1 of 6)	
Size	Document Number	Rev	SA
Date: Thursday, March 01, 2007	Biwa	Sheet 6 of 42	



FOR Calero: 255 ohm  
 Crestline: 1.3k ohm  
 CRT IREF routing Trace  
 width use 20 mil

12 M\_A\_DQ[63..0] <<>> M\_A\_DQ[63..0]

M_A DQ0	AR43	SA_DQ0
M_A DQ1	AW44	SA_DQ1
M_A DQ2	BA45	SA_DQ2
M_A DQ3	AY46	SA_DQ3
M_A DQ4	AR41	SA_DQ4
M_A DQ5	AR45	SA_DQ5
M_A DQ6	AT42	SA_DQ6
M_A DQ7	AW47	SA_DQ7
M_A DQ8	BB45	SA_DQ8
M_A DQ9	BF48	SA_DQ9
M_A DQ10	BG47	SA_DQ10
M_A DQ11	BH45	SA_DQ11
M_A DQ12	BB47	SA_DQ12
M_A DQ13	BG50	SA_DQ13
M_A DQ14	BH49	SA_DQ14
M_A DQ15	BE45	SA_DQ15
M_A DQ16	AW43	SA_DQ16
M_A DQ17	BE44	SA_DQ17
M_A DQ18	BG42	SA_DQ18
M_A DQ19	BE40	SA_DQ19
M_A DQ20	BF44	SA_DQ20
M_A DQ21	BH45	SA_DQ21
M_A DQ22	BG40	SA_DQ22
M_A DQ23	AR40	SA_DQ23
M_A DQ24	AW40	SA_DQ24
M_A DQ25	AT39	SA_DQ25
M_A DQ26	AW36	SA_DQ26
M_A DQ27	AW36	SA_DQ27
M_A DQ28	AW41	SA_DQ28
M_A DQ29	AY41	SA_DQ29
M_A DQ30	AV38	SA_DQ30
M_A DQ31	AT38	SA_DQ31
M_A DQ32	AV13	SA_DQ32
M_A DQ33	AT13	SA_DQ33
M_A DQ34	AW11	SA_DQ34
M_A DQ35	AV11	SA_DQ35
M_A DQ36	AU15	SA_DQ36
M_A DQ37	AT11	SA_DQ37
M_A DQ38	BA13	SA_DQ38
M_A DQ39	BA11	SA_DQ39
M_A DQ40	BE10	SA_DQ40
M_A DQ41	BD10	SA_DQ41
M_A DQ42	BD8	SA_DQ42
M_A DQ43	AY3	SA_DQ43
M_A DQ44	BG10	SA_DQ44
M_A DQ45	AW9	SA_DQ45
M_A DQ46	BD7	SA_DQ46
M_A DQ47	BB9	SA_DQ47
M_A DQ48	BB5	SA_DQ48
M_A DQ49	AY7	SA_DQ49
M_A DQ50	AT5	SA_DQ50
M_A DQ51	AT7	SA_DQ51
M_A DQ52	AY6	SA_DQ52
M_A DQ53	BB7	SA_DQ53
M_A DQ54	AR5	SA_DQ54
M_A DQ55	AR8	SA_DQ55
M_A DQ56	AR3	SA_DQ56
M_A DQ57	AM8	SA_DQ57
M_A DQ58	AN10	SA_DQ58
M_A DQ59	AT9	SA_DQ59
M_A DQ60	AN9	SA_DQ60
M_A DQ61	AM9	SA_DQ61
M_A DQ62	AN11	SA_DQ62
M_A DQ63	AN11	SA_DQ63

SA_BSO	BB19	M_A_BS#0 12,13
SA_BS1	BK19	M_A_BS#1 12,13
SA_BS2	BF29	M_A_BS#2 12,13
		M_A_CAS# 12,13
SA_CAS#	BL17	M_A_DM[7..0] 12
		M_A_DM0
SA_DM0	AT45	M_A_DM1
SA_DM1	BD44	M_A_DM2
SA_DM2	BD42	M_A_DM3
SA_DM3	AW38	M_A_DM4
SA_DM4	AW13	M_A_DM5
SA_DM5	BG8	M_A_DM6
SA_DM6	AY5	M_A_DM7
SA_DM7	AN6	
		M_A_DQS[7..0] 12
SA_DQS0	AT46	M_A_DQS1
SA_DQS1	BE48	M_A_DQS2
SA_DQS2	BE43	M_A_DQS3
SA_DQS3	BC37	M_A_DQS4
SA_DQS4	BB16	M_A_DQS5
SA_DQS5	BH6	M_A_DQS6
SA_DQS6	BB2	M_A_DQS7
SA_DQS7	AP3	
		M_A_DQS# [7..0] 12
SA_DQS#0	AT47	M_A_DQS#1
SA_DQS#1	BD47	M_A_DQS#2
SA_DQS#2	BC41	M_A_DQS#3
SA_DQS#3	BA37	M_A_DQS#4
SA_DQS#4	BA16	M_A_DQS#5
SA_DQS#5	BH7	M_A_DQS#6
SA_DQS#6	BC1	M_A_DQS#7
SA_DQS#7	AP2	
		M_A_A[14..0] 12,13
SA_MA0	BJ19	M_A_A0
SA_MA1	BD20	M_A_A1
SA_MA2	BK27	M_A_A2
SA_MA3	BH28	M_A_A3
SA_MA4	BL24	M_A_A4
SA_MA5	BK28	M_A_A5
SA_MA6	BJ27	M_A_A6
SA_MA7	BJ25	M_A_A7
SA_MA8	BL28	M_A_A8
SA_MA9	BA28	M_A_A9
SA_MA10	BC19	M_A_A10
SA_MA11	BE28	M_A_A11
SA_MA12	BG30	M_A_A12
SA_MA13	BL16	M_A_A13
SA_MA14	BJ29	M_A_A14
		M_A_RAS# 12,13
SA_RAS#	BE18	
SA_RCVEN#	AY20	SA_RCVEN#
		M_A_WE# 12,13
SA_WE#	BA19	

DDR SYSTEM MEMORY A

Place Test PAD Near to Chip as could as possible



12 M\_B\_DQ[63..0] <<>> M\_B\_DQ[63..0]

M_B DQ0	AP49	SB_DQ0
M_B DQ1	AR51	SB_DQ1
M_B DQ2	AW50	SB_DQ2
M_B DQ3	AW51	SB_DQ3
M_B DQ4	AN51	SB_DQ4
M_B DQ5	AN50	SB_DQ5
M_B DQ6	AV50	SB_DQ6
M_B DQ7	AV49	SB_DQ7
M_B DQ8	BA50	SB_DQ8
M_B DQ9	BB50	SB_DQ9
M_B DQ10	BE50	SB_DQ10
M_B DQ11	BE51	SB_DQ11
M_B DQ12	BA51	SB_DQ12
M_B DQ13	AY49	SB_DQ13
M_B DQ14	BF50	SB_DQ14
M_B DQ15	BF49	SB_DQ15
M_B DQ16	BJ50	SB_DQ16
M_B DQ17	BJ44	SB_DQ17
M_B DQ18	BJ43	SB_DQ18
M_B DQ19	BL43	SB_DQ19
M_B DQ20	BK47	SB_DQ20
M_B DQ21	BK49	SB_DQ21
M_B DQ22	BK42	SB_DQ22
M_B DQ23	BK43	SB_DQ23
M_B DQ24	BJ41	SB_DQ24
M_B DQ25	BL41	SB_DQ25
M_B DQ26	BJ37	SB_DQ26
M_B DQ27	BJ36	SB_DQ27
M_B DQ28	BK41	SB_DQ28
M_B DQ29	BJ40	SB_DQ29
M_B DQ30	BL35	SB_DQ30
M_B DQ31	BK37	SB_DQ31
M_B DQ32	BE13	SB_DQ32
M_B DQ33	BE11	SB_DQ33
M_B DQ34	BK11	SB_DQ34
M_B DQ35	BC11	SB_DQ35
M_B DQ36	BC13	SB_DQ36
M_B DQ37	BE12	SB_DQ37
M_B DQ38	BC12	SB_DQ38
M_B DQ39	BG12	SB_DQ39
M_B DQ40	BJ10	SB_DQ40
M_B DQ41	BL9	SB_DQ41
M_B DQ42	BK5	SB_DQ42
M_B DQ43	BL5	SB_DQ43
M_B DQ44	BK9	SB_DQ44
M_B DQ45	BK10	SB_DQ45
M_B DQ46	BJ8	SB_DQ46
M_B DQ47	BJ6	SB_DQ47
M_B DQ48	BF4	SB_DQ48
M_B DQ49	BH5	SB_DQ49
M_B DQ50	BG1	SB_DQ50
M_B DQ51	BC2	SB_DQ51
M_B DQ52	BK3	SB_DQ52
M_B DQ53	BE4	SB_DQ53
M_B DQ54	BD3	SB_DQ54
M_B DQ55	BJ2	SB_DQ55
M_B DQ56	BA3	SB_DQ56
M_B DQ57	BB3	SB_DQ57
M_B DQ58	AR1	SB_DQ58
M_B DQ59	AT3	SB_DQ59
M_B DQ60	AY2	SB_DQ60
M_B DQ61	AY3	SB_DQ61
M_B DQ62	AJ2	SB_DQ62
M_B DQ63	AT2	SB_DQ63

U40E 5 OF 10

DDR SYSTEM MEMORY B

SB_BSO	AY17	M_B_BS#0 12,13
SB_BS1	BG18	M_B_BS#1 12,13
SB_BS2	BG38	M_B_BS#2 12,13
		M_B_CAS# 12,13
SB_CAS#	BE17	M_B_DM[7..0] 12
		M_B_DM0
SB_DM0	AR50	M_B_DM1
SB_DM1	BD49	M_B_DM2
SB_DM2	BK45	M_B_DM3
SB_DM3	BL39	M_B_DM4
SB_DM4	BH12	M_B_DM5
SB_DM5	BL7	M_B_DM6
SB_DM6	BF3	M_B_DM7
SB_DM7	AW2	
		M_B_DQS[7..0] 12
SB_DQS0	AT50	M_B_DQS1
SB_DQS1	BD50	M_B_DQS2
SB_DQS2	BK46	M_B_DQS3
SB_DQS3	BK39	M_B_DQS4
SB_DQS4	BJ12	M_B_DQS5
SB_DQS5	BL7	M_B_DQS6
SB_DQS6	BE2	M_B_DQS7
SB_DQS7	AV2	
		M_B_DQS# [7..0] 12
SB_DQS#0	AU50	M_B_DQS#1
SB_DQS#1	BC45	M_B_DQS#2
SB_DQS#2	BK38	M_B_DQS#3
SB_DQS#3	BK12	M_B_DQS#4
SB_DQS#4	BK7	M_B_DQS#5
SB_DQS#5	BF2	M_B_DQS#6
SB_DQS#6	AV3	M_B_DQS#7
SB_DQS#7		
		M_B_A[14..0] 12,13
SB_MA0	BC18	M_B_A0
SB_MA1	BG28	M_B_A1
SB_MA2	BG25	M_B_A2
SB_MA3	AW17	M_B_A3
SB_MA4	BE25	M_B_A4
SB_MA5	BA29	M_B_A5
SB_MA6	BC28	M_B_A6
SB_MA7	AY28	M_B_A7
SB_MA8	BD37	M_B_A8
SB_MA9	BG17	M_B_A9
SB_MA10	BE37	M_B_A10
SB_MA11	BA39	M_B_A11
SB_MA12	BG13	M_B_A12
SB_MA13	BE24	M_B_A13
SB_MA14	BE24	M_B_A14
		M_B_RAS# 12,13
SB_RAS#	AV16	
SB_RCVEN#	AY18	SB_RCVEN#
		M_B_WE# 12,13
SB_WE#	BC17	

Place Test PAD Near to Chip as could as possible

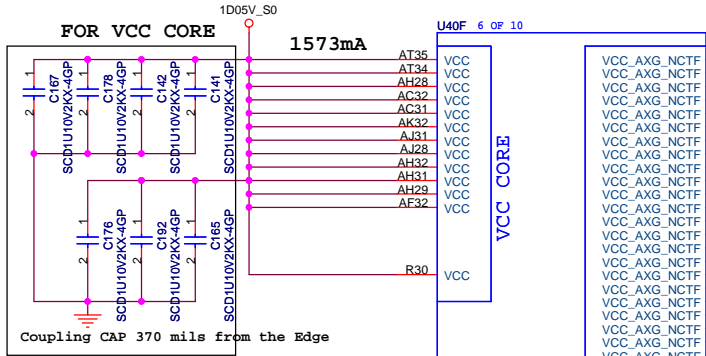


緯創資通 Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

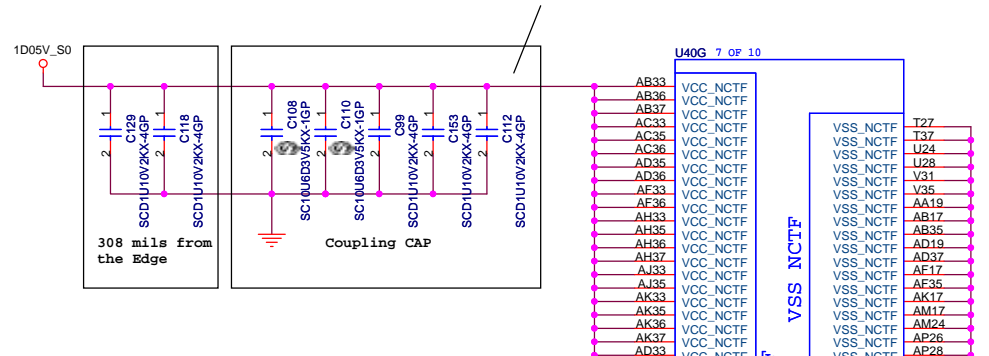
Title: GMCH (3 of 6)  
 Size: Document Number  
 Date: Thursday, March 01, 2007 Sheet 8 of 42  
 Rev: SA



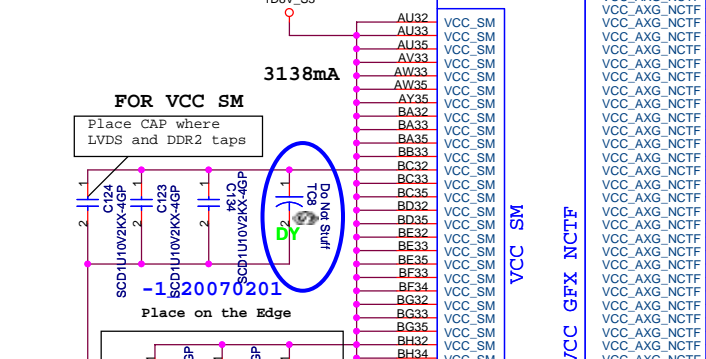
VCC\_NCTF + VCC=1573mA

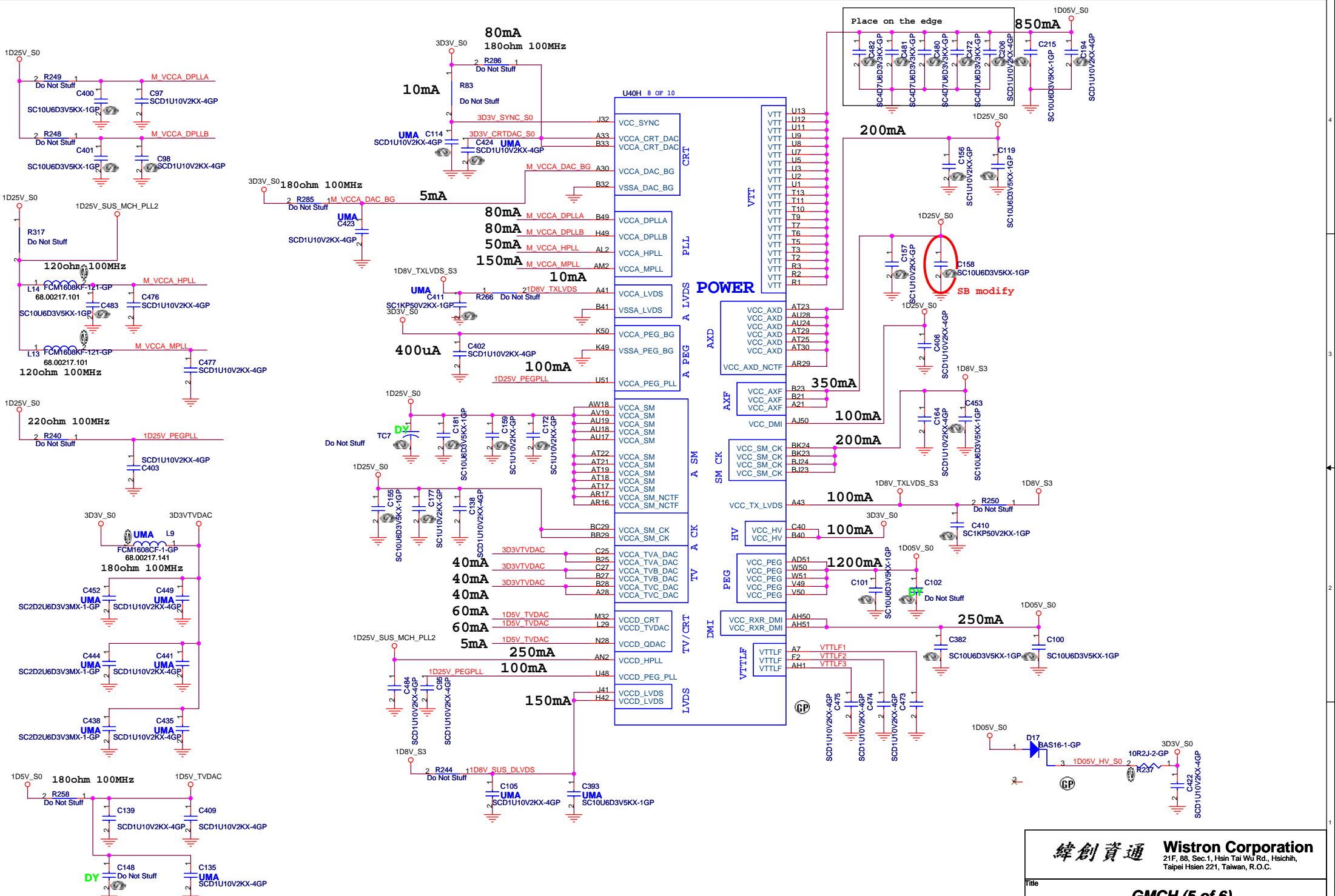


FOR VCC CORE AND VCC NCTF



VCC AXG\_NCTF + VCC AXG=7700mA

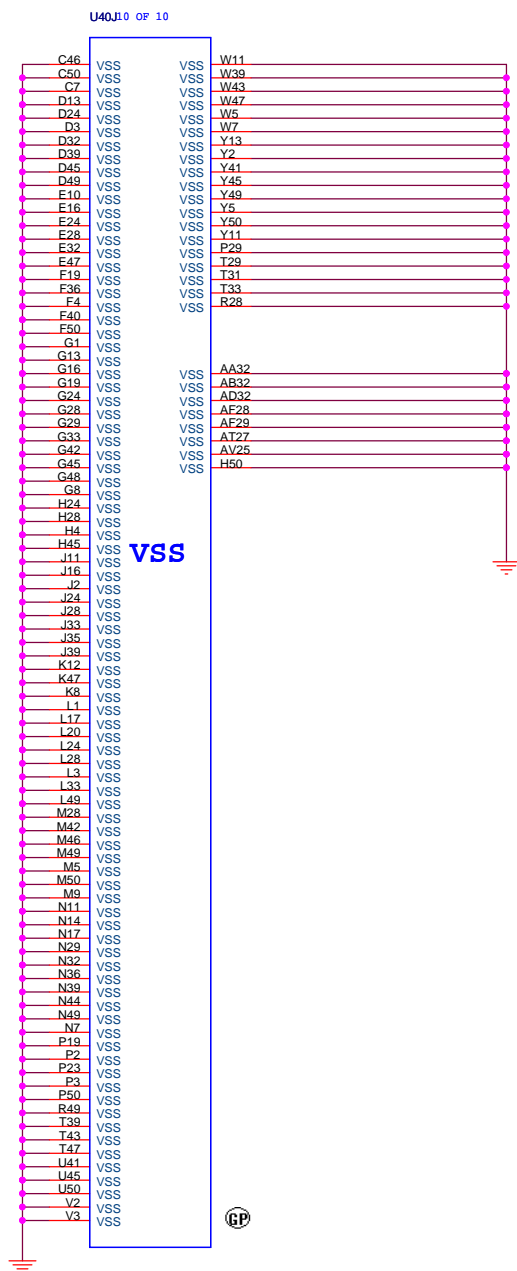
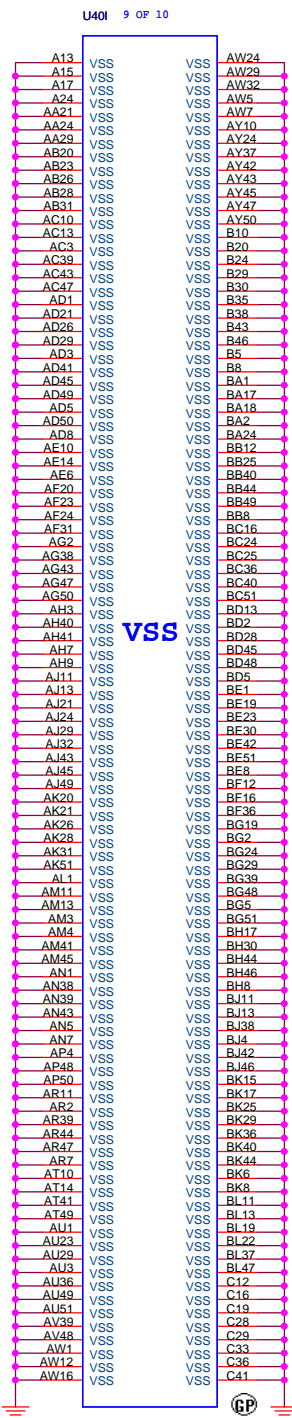




緯創資通 Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title		<b>GMCH (5 of 6)</b>	
Size	Document Number	Rev	
Date: Thursday, March 01, 2007		<b>Biwa</b>	
Sheet 10 of 42		<b>SB</b>	

hexainf@hotmail.com  
 GRATIS - FOR FREE

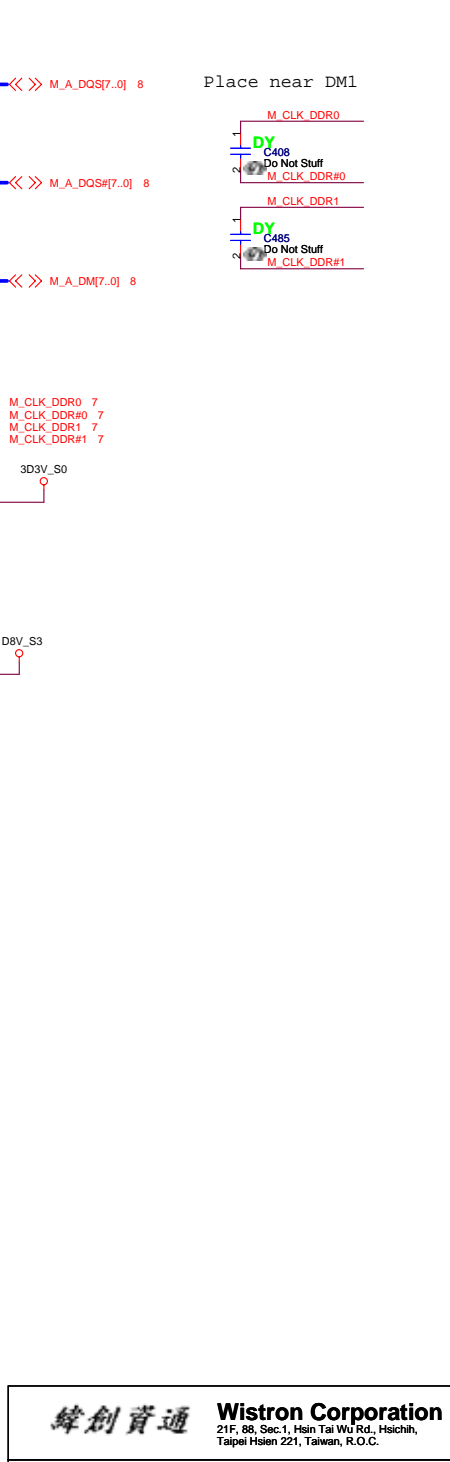
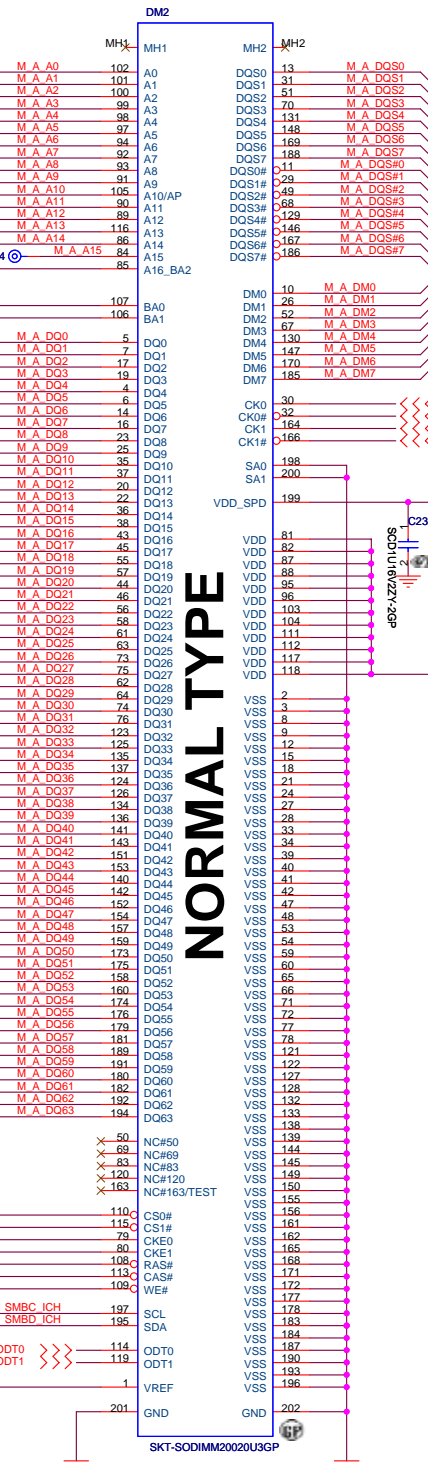
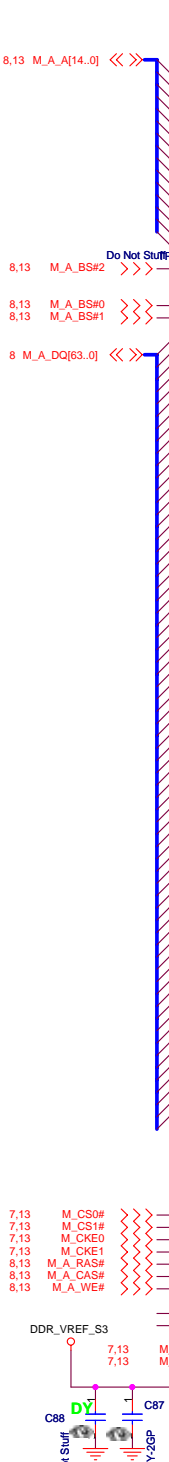
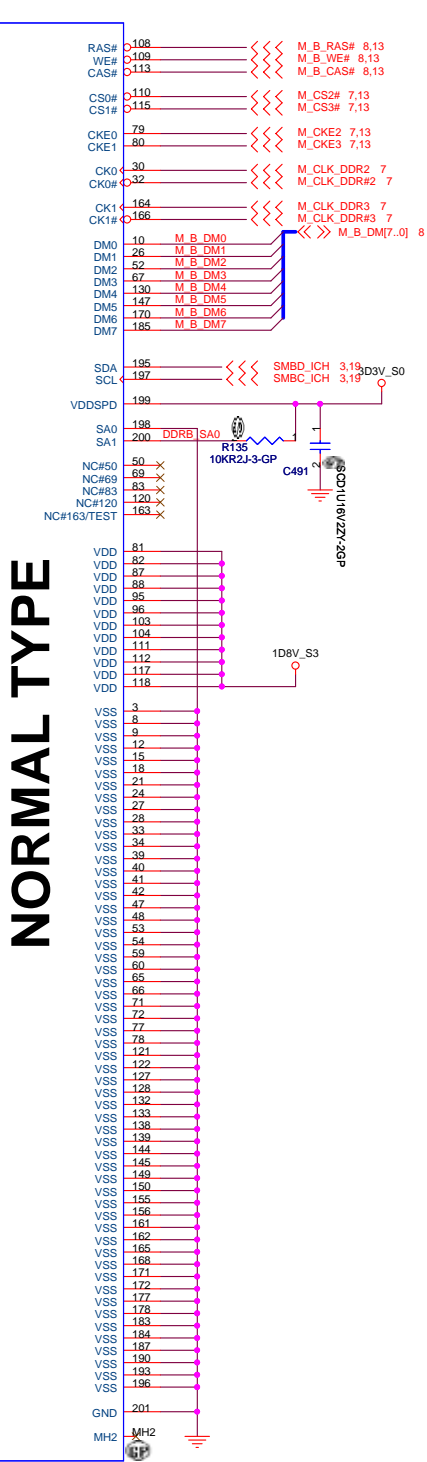
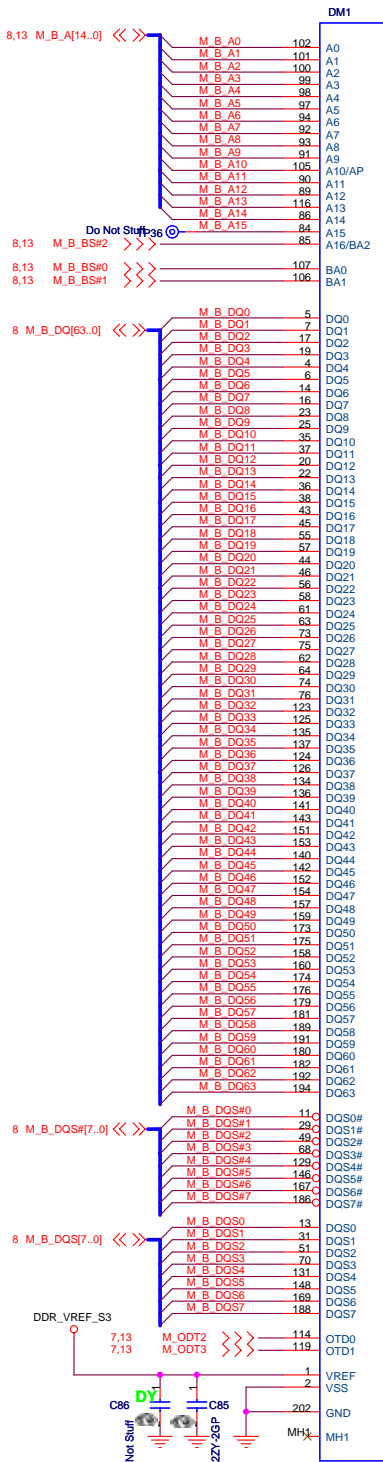


VSS

VSS



<b>緯創資通 Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
<b>GMCH (6 of 6)</b>	
Size	Document Number
<b>Biwa</b>	
Date: Thursday, March 01, 2007	Rev SA
Sheet 11	of 42



**NORMAL TYPE**

**NORMAL TYPE**

Place near DM1

Place near DM2

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

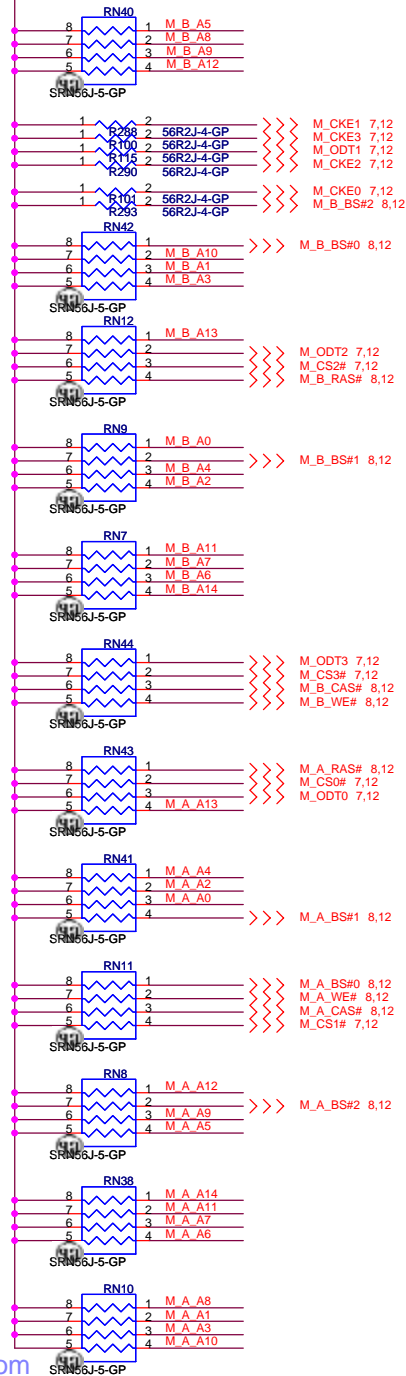
Title: **DDR2 Socket**

Size: Document Number: **Biwa** Rev: SA

Date: Thursday, March 01, 2007 Sheet 12 of 42

# PARALLEL TERMINATION

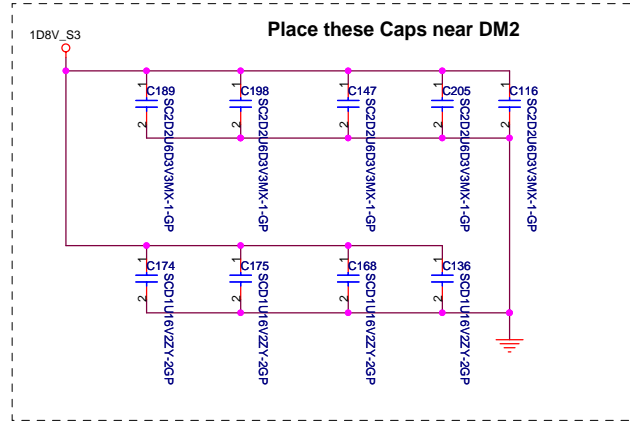
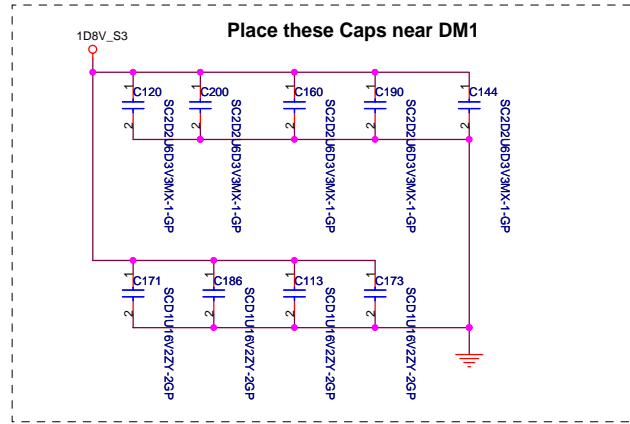
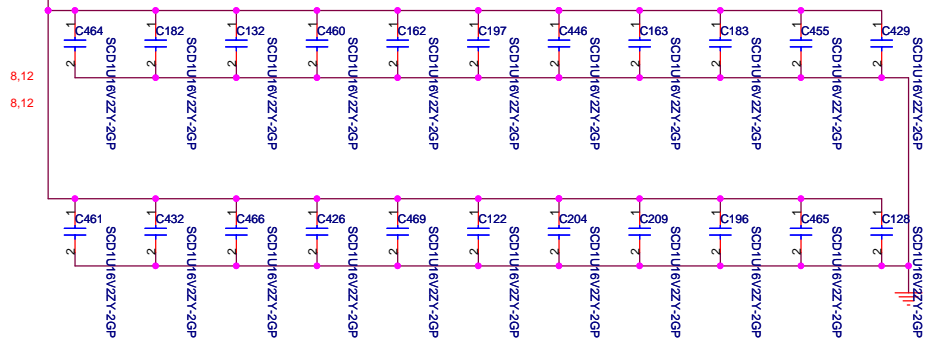
DDR\_VREF\_S0 Put decap near power(0.9V) and pull-up resistor



M\_A A[14..0] <<> M\_A\_A[14..0] 8,12  
M\_B A[14..0] <<> M\_B\_B\_A[14..0] 8,12

# Decoupling Capacitor

Put decap near power(0.9V) and pull-up resistor



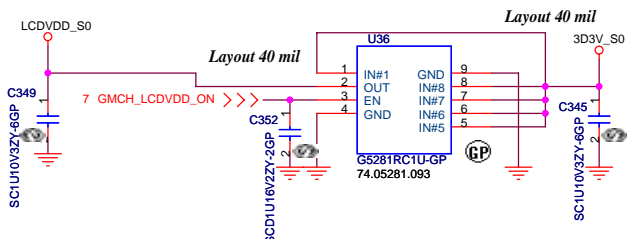
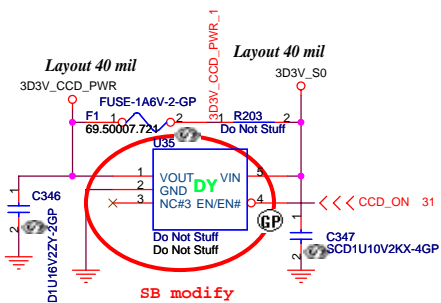
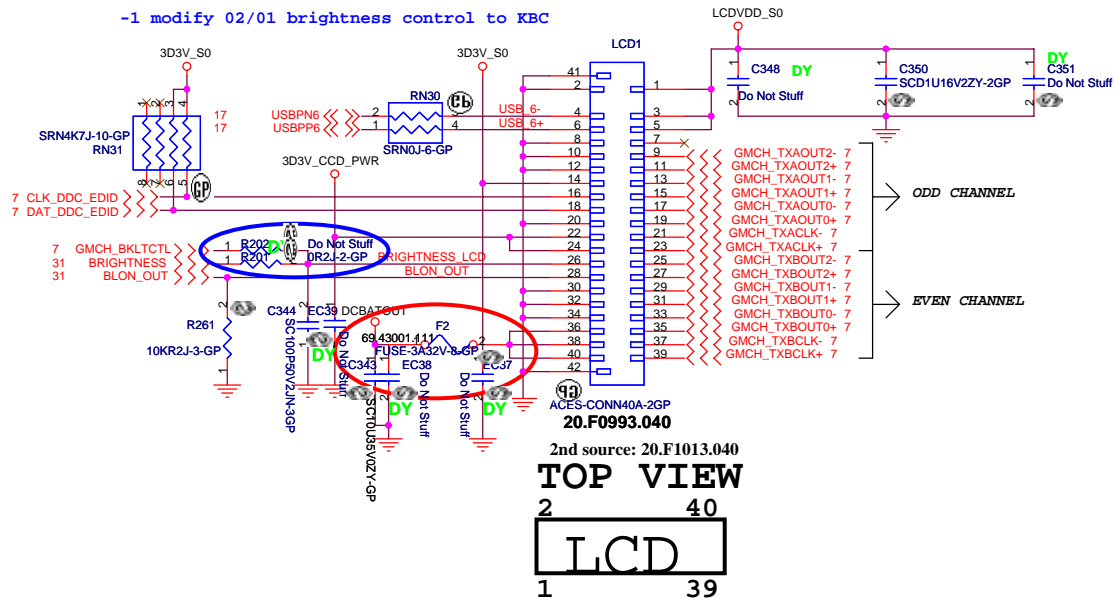
緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **DDR2 Termination Resistor**

Size: Document Number **Biwa** Rev: **SB**

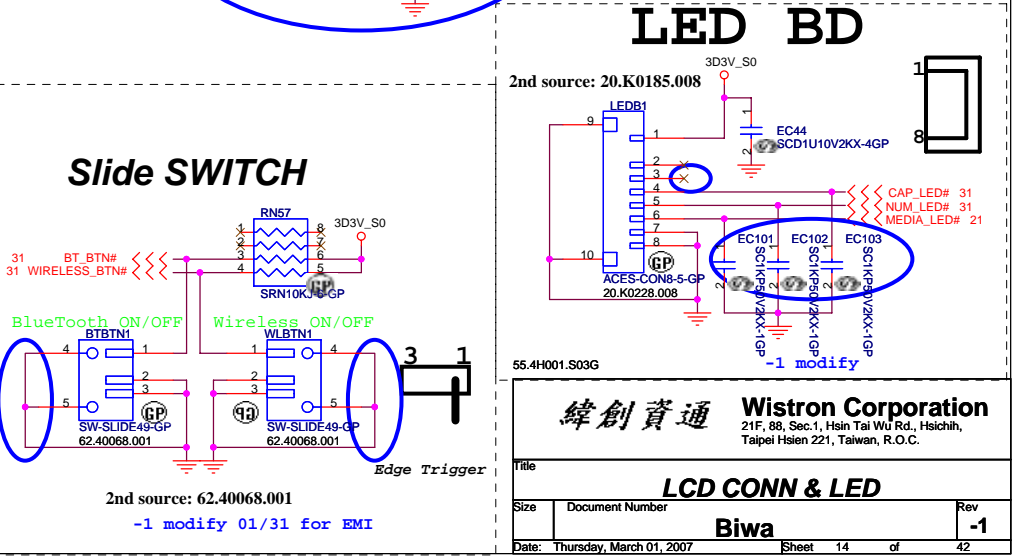
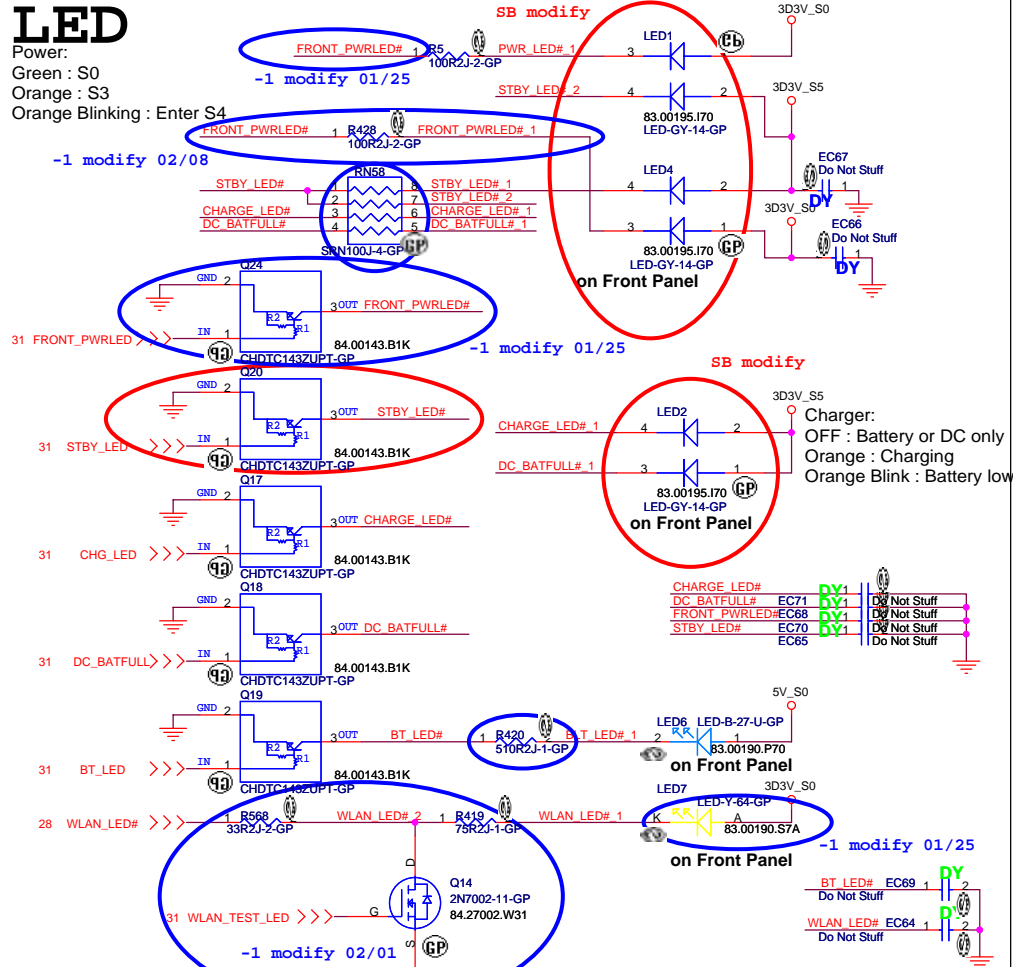
Date: Thursday, March 01, 2007 Sheet 13 of 42

-1 modify 02/01 brightness control to KBC



# LED

Power: Green : S0 Orange : S3 Orange Blinking : Enter S4



## LED BD

2nd source: 20.K0185.008

CAP\_LED# 31  
NUM\_LED# 31  
MEDIA\_LED# 21

55.4H001.S03G  
-1 modify

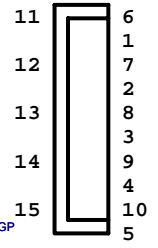
**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

**LCD CONN & LED**

File	Document Number	Rev
		-1

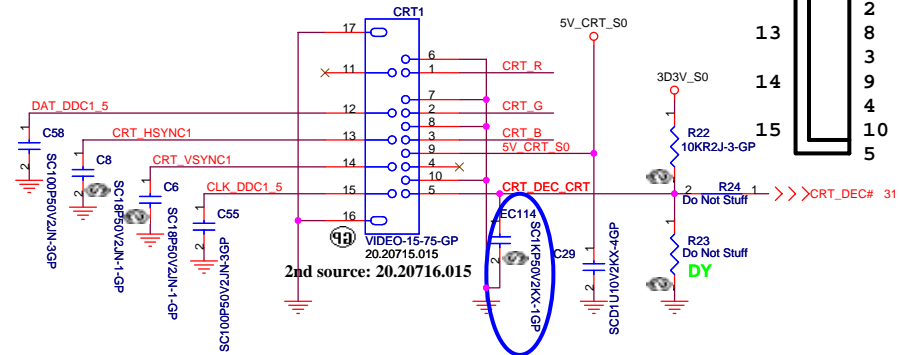
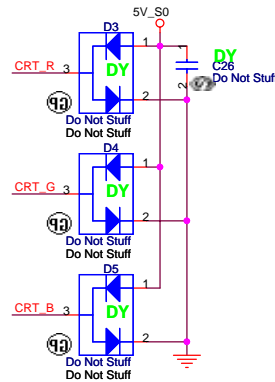
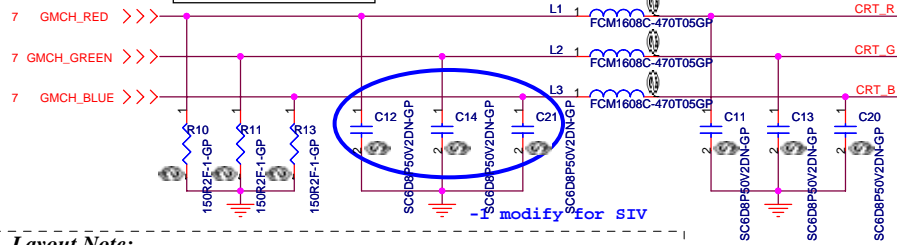
Date: Thursday, March 01, 2007 Sheet 14 of 42

# CRT I/F & CONNECTOR



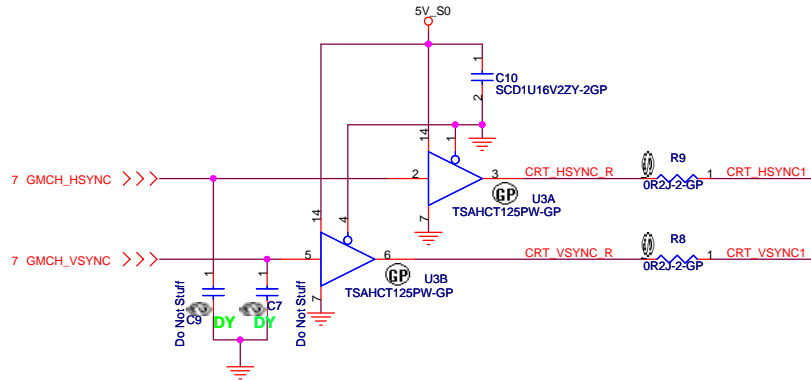
Layout Note:  
Place these resistors close to the CRT-out connector

Ferrite bead impedance: 47 ohm@100MHz

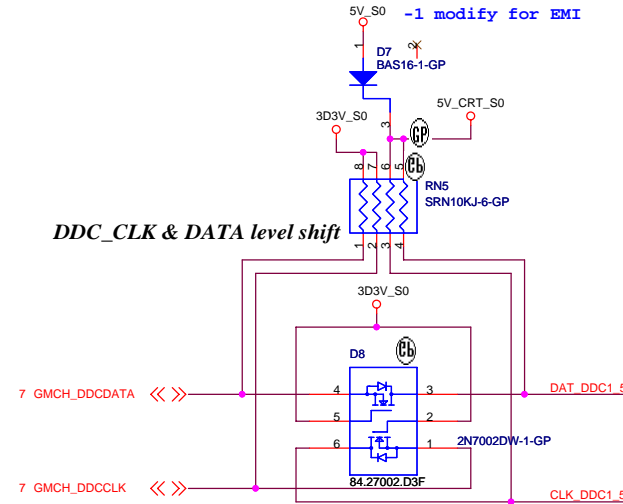


Layout Note:  
\* Must be a ground return path between this ground and the ground on the VGA connector.  
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

## Hsync & Vsync level shift

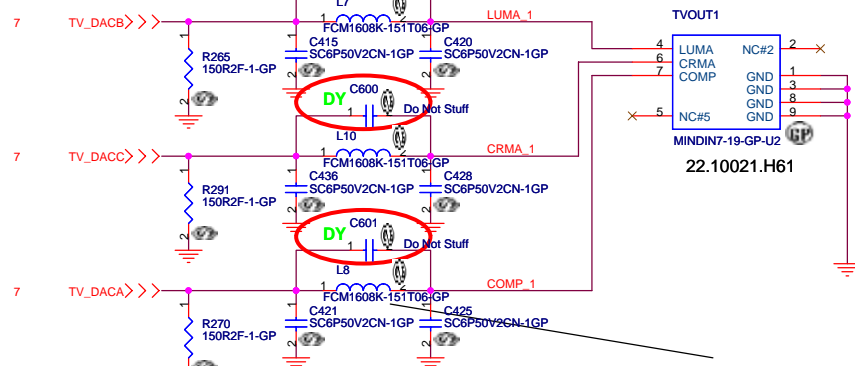


## DDC\_CLK & DATA level shift

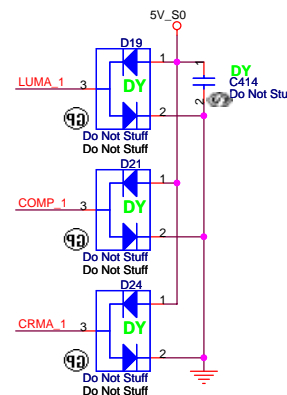


## TV CONN

SB modify for SIV



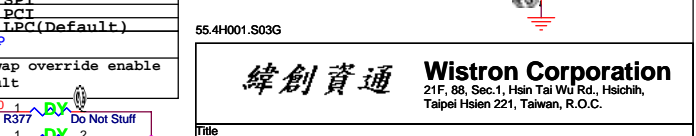
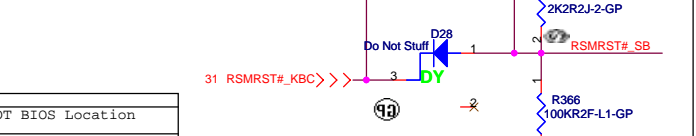
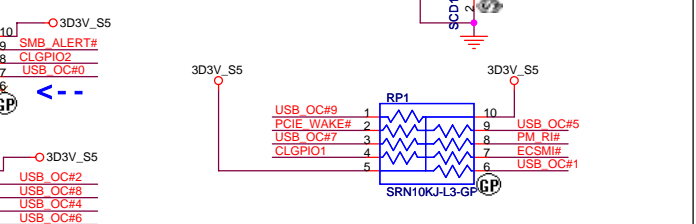
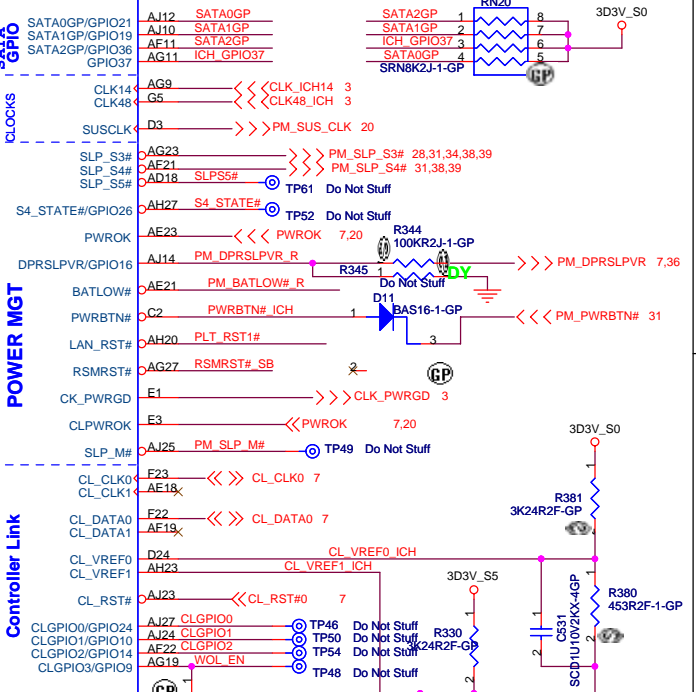
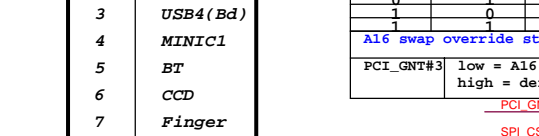
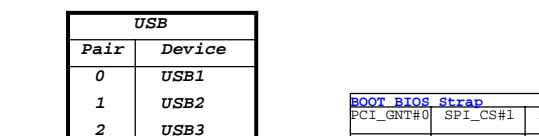
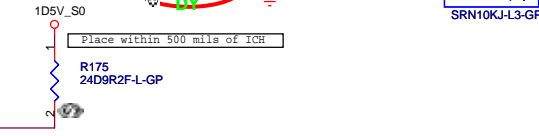
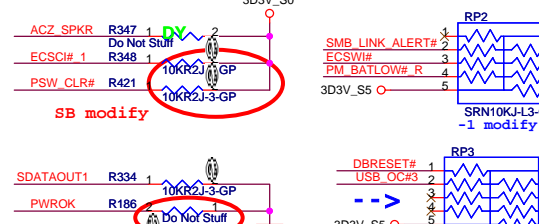
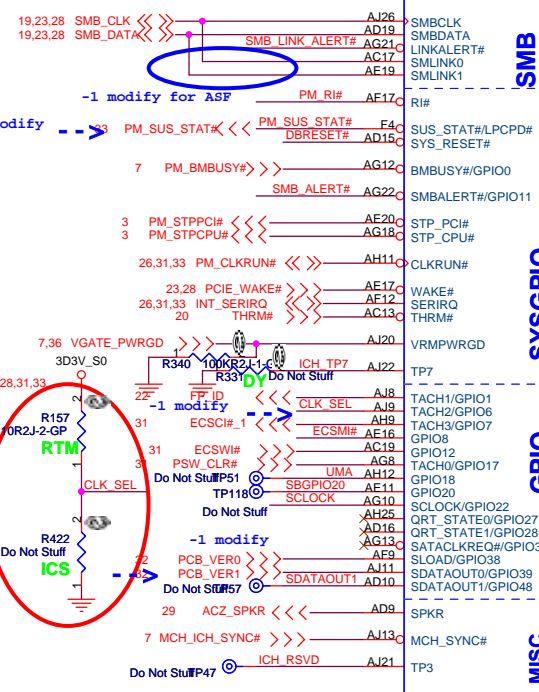
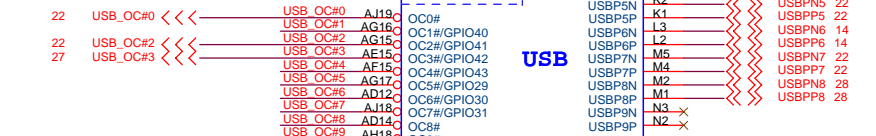
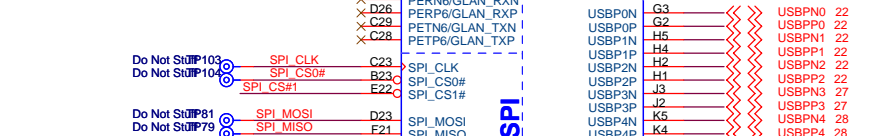
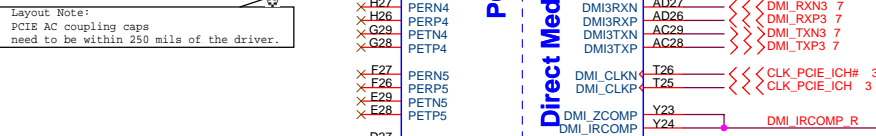
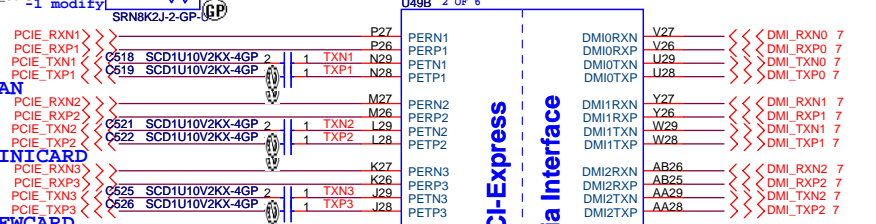
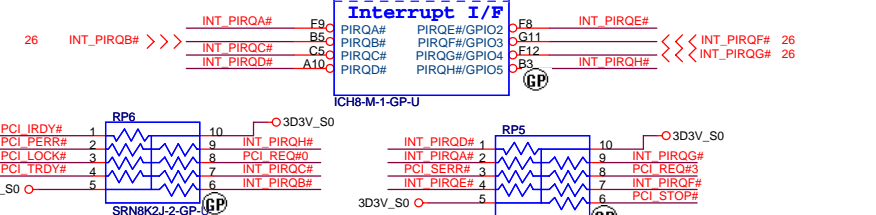
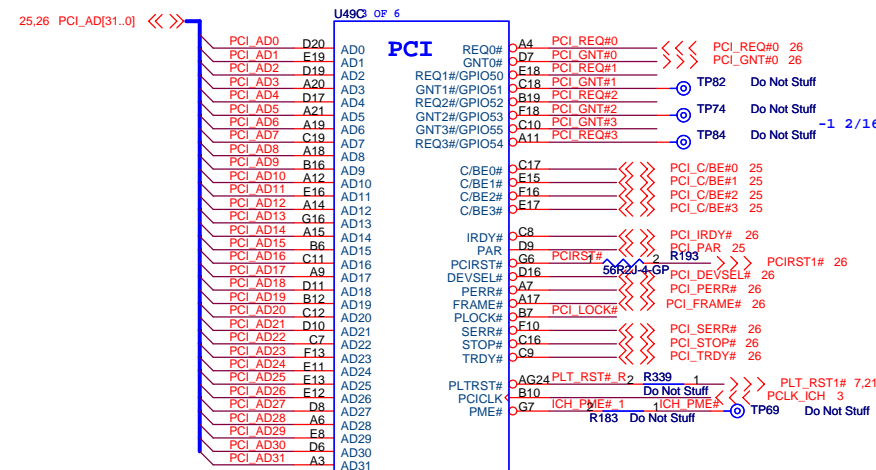
Ferrite bead impedance: 150 ohm@100MHz; 100mA(min) design recommend



<p>緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</p>	
Title	CRT/TV Connector
Size	Document Number
Date	Thursday, March 01, 2007
Sheet	15 of 42
Rev	-1







Pair	Device
0	USB1
1	USB2
2	USB3
3	USB4 (Bd)
4	MINIC1
5	BT
6	CCD
7	Finger
8	New
9	NC

Pair	Device
0	USB1
1	USB2
2	USB3
3	USB4 (Bd)
4	MINIC1
5	BT
6	CCD
7	Finger
8	New
9	NC

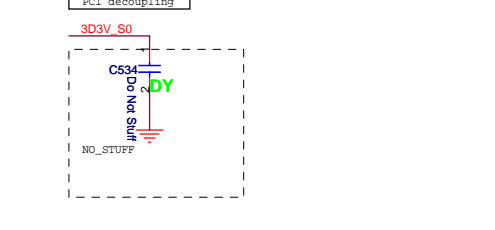
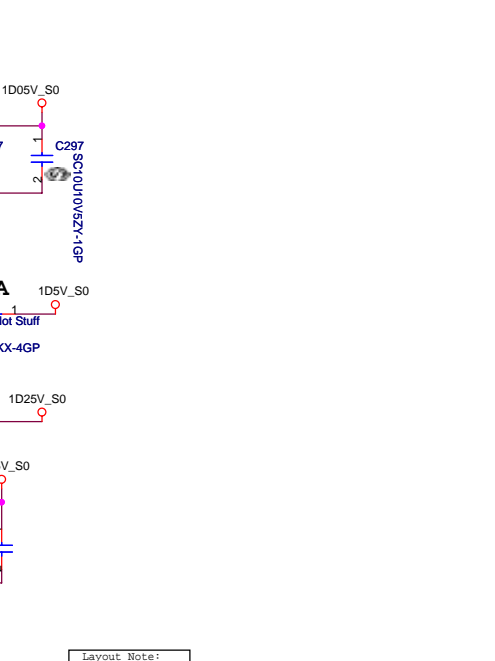
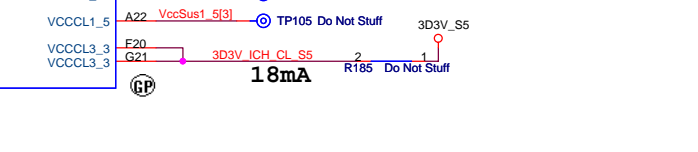
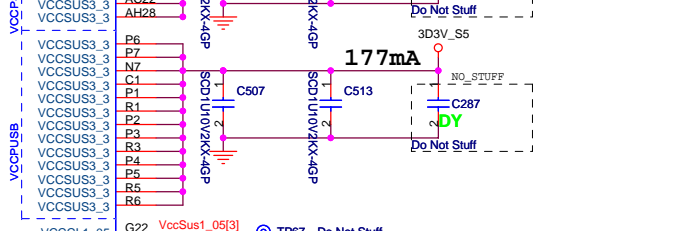
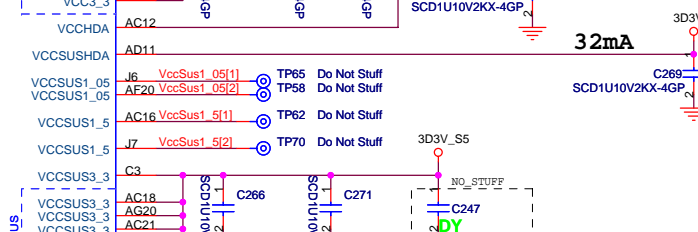
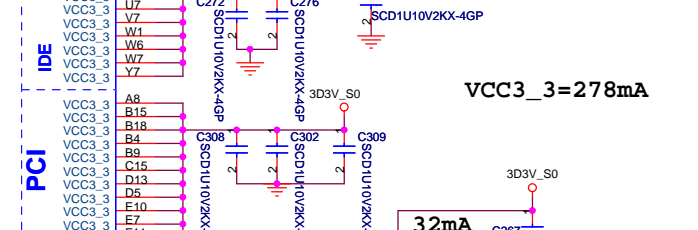
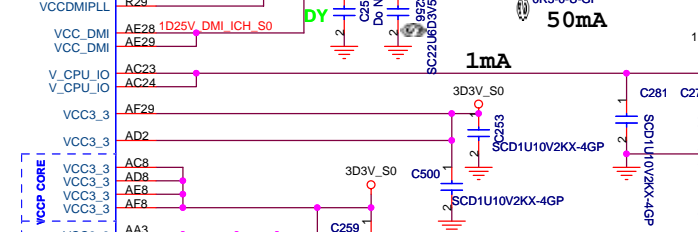
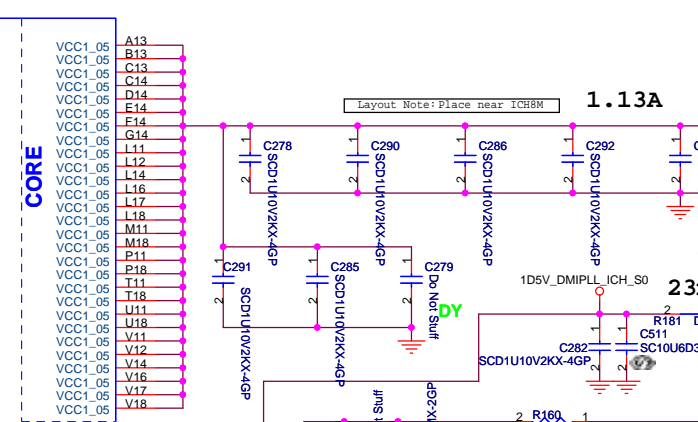
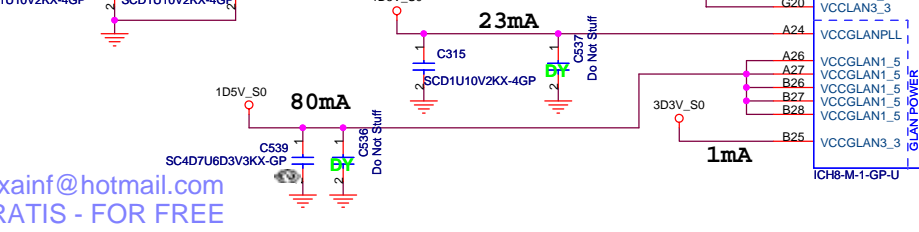
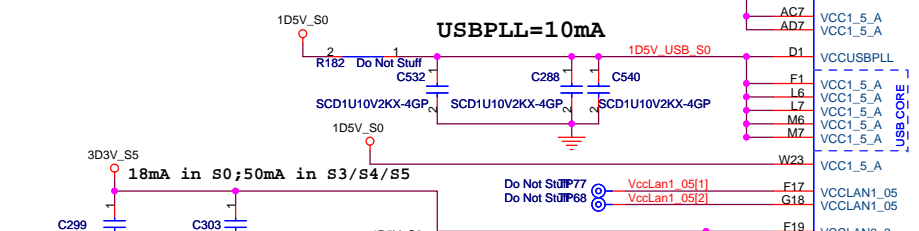
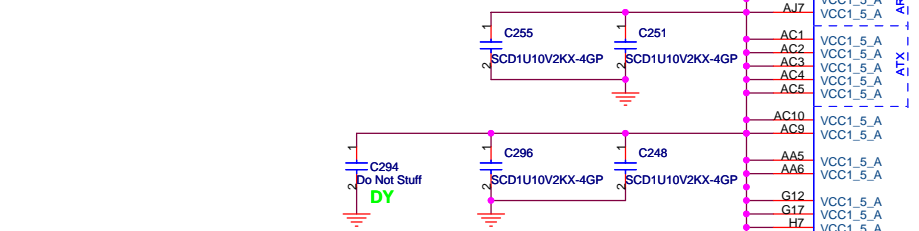
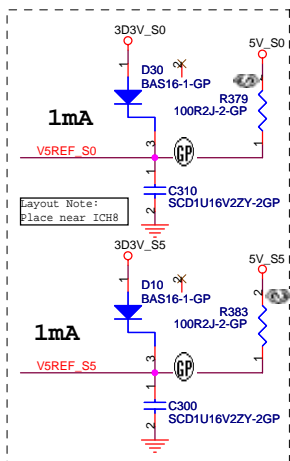
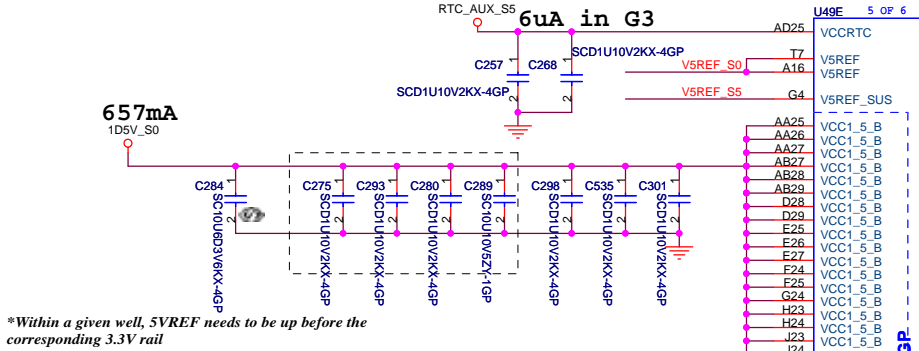
55.4H001.S03G

**緯創資通 Wistron Corporation**  
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

**ICH8-M (2 of 4)**

**Biwa**

Date: Thursday, March 01, 2007 Sheet 17 of 42



**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

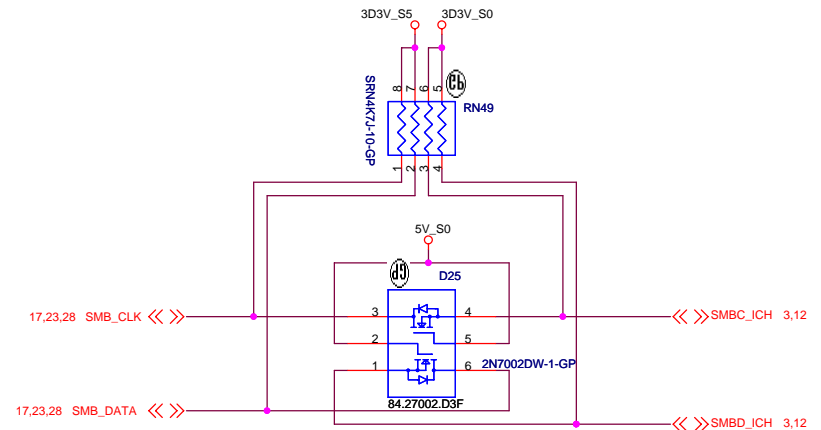
File	<b>ICH8-M (3 of 4)</b>	
Size	Document Number	Rev
		<b>SB</b>
Date: Thursday, March 01, 2007	Sheet 18 of 42	

hexainf@hotmail.com  
GRATIS - FOR FREE

U49F 6 OF 6

A23	VSS	K7
A5	VSS	L1
AA2	VSS	L13
AA7	VSS	L15
A25	VSS	L26
AB1	VSS	L27
AB24	VSS	L4
AC11	VSS	L5
AC14	VSS	M12
AC25	VSS	M13
AC26	VSS	M14
AC27	VSS	M15
AD17	VSS	M16
AD20	VSS	M17
AD28	VSS	M23
AD29	VSS	M28
AD3	VSS	M29
AD4	VSS	M3
AD6	VSS	N1
AE1	VSS	N11
AE12	VSS	N12
AE2	VSS	N13
AE22	VSS	N14
AD1	VSS	N15
AE25	VSS	N16
AE5	VSS	N17
AE6	VSS	N18
AE9	VSS	N26
AF14	VSS	N27
AF16	VSS	N4
AF18	VSS	N5
AF3	VSS	N6
AF4	VSS	P12
AG5	VSS	P13
AG6	VSS	P14
AH10	VSS	P15
AH13	VSS	P16
AH16	VSS	P17
AH19	VSS	P23
AH2	VSS	P28
AE28	VSS	P29
AH22	VSS	R11
AH24	VSS	R12
AH26	VSS	R13
AH3	VSS	R14
AH4	VSS	R15
AH8	VSS	R16
AJ5	VSS	R17
B11	VSS	R18
B14	VSS	R28
B17	VSS	R4
B2	VSS	T12
B20	VSS	T13
B22	VSS	T14
B3	VSS	T15
C24	VSS	T16
C26	VSS	T17
C27	VSS	T2
C6	VSS	U12
D12	VSS	U13
D15	VSS	U14
D18	VSS	U15
D2	VSS	U16
D4	VSS	U17
E21	VSS	U23
E24	VSS	U26
E4	VSS	U27
E9	VSS	U3
F15	VSS	U5
E23	VSS	V13
F28	VSS	V15
F29	VSS	V28
F7	VSS	V29
G1	VSS	W2
F2	VSS	W26
G10	VSS	W27
G13	VSS	Y28
G19	VSS	Y29
G23	VSS	Y4
G25	VSS	AB4
G26	VSS	AB23
G27	VSS	AB5
H25	VSS	AB6
H28	VSS	AD5
H29	VSS	U4
H3	VSS	W24
H6	VSS	A1
J1	VSS	A2
J25	VSS_NCTF	A28
J26	VSS_NCTF	A29
J27	VSS_NCTF	AJ28
J4	VSS_NCTF	AH1
J5	VSS_NCTF	AH29
K23	VSS_NCTF	AJ1
K28	VSS_NCTF	AJ2
K29	VSS_NCTF	AJ29
K3	VSS_NCTF	B1
K6	VSS_NCTF	B29
	VSS_NCTF	A1
	VSS_NCTF	A2
	VSS_NCTF	A28
	VSS_NCTF	A29
	VSS_NCTF	AJ28
	VSS_NCTF	AH1
	VSS_NCTF	AH29
	VSS_NCTF	AJ1
	VSS_NCTF	AJ2
	VSS_NCTF	AJ29
	VSS_NCTF	B1
	VSS_NCTF	B29

ICH8-M-1-GP-U



D55 connect SMLINK and SMBUS in S) for SMBus 2.0 compliance

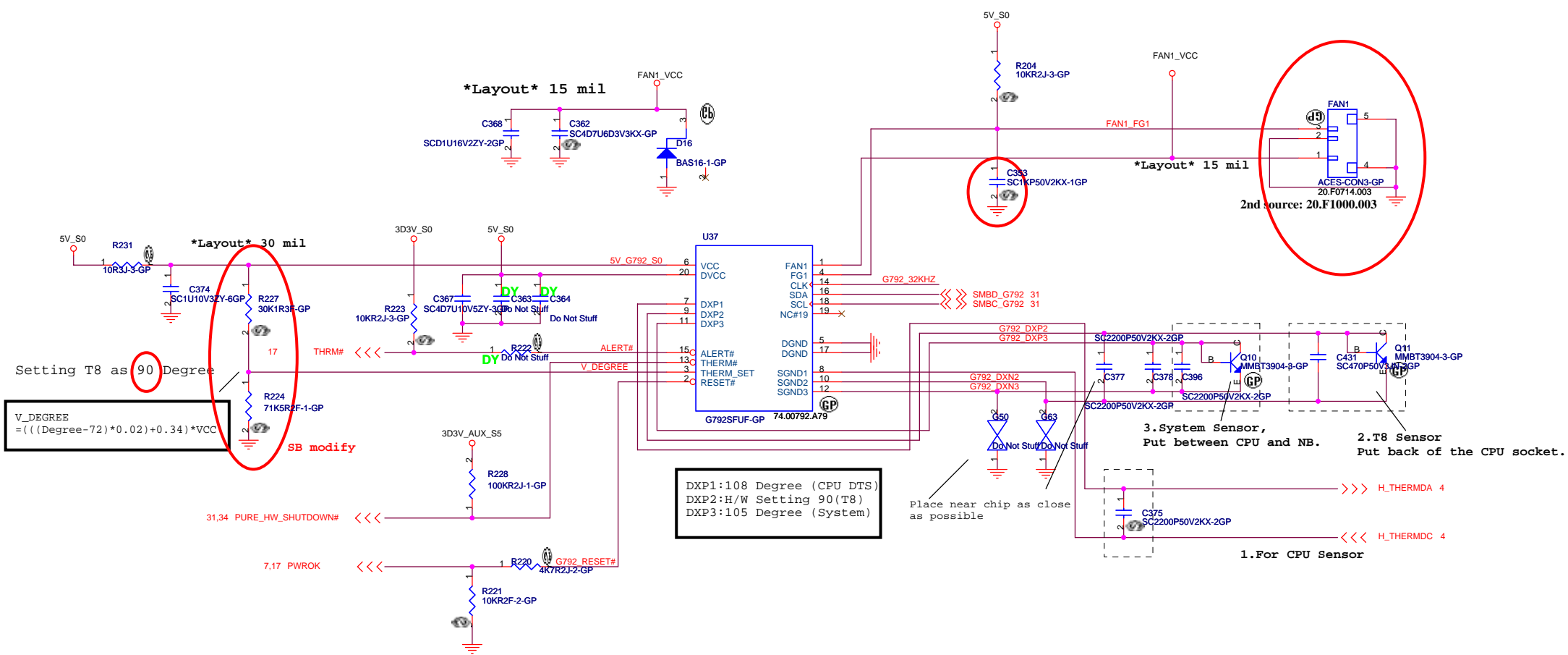
**SMBUS**

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **ICH8-M (4 of 4)**

Size: Document Number: **Biwa** Rev: SA

Date: Thursday, March 01, 2007 Sheet 19 of 42



Setting T8 as 90 Degree

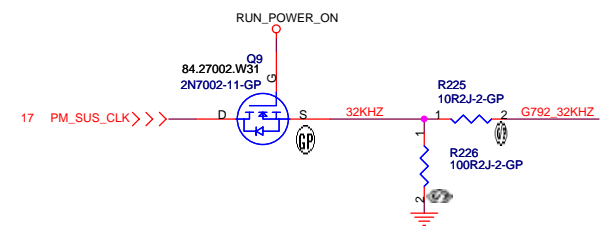
$$V\_DEGREE = (((Degree - 72) * 0.02) + 0.34) * VCC$$

SB modify

DXP1: 108 Degree (CPU DTS)  
 DXP2: H/W Setting 90 (T8)  
 DXP3: 105 Degree (System)

- 3. System Sensor, Put between CPU and NB.
- 2. T8 Sensor Put back of the CPU socket.
- 1. For CPU Sensor

TEMP.	Digital Output Data Bits			
	Sign	MSB	LSB	EXT
+127.875	0	111	1111	111
+126.375	0	111	1110	011
+25.5	0	001	1001	100
+1.75	0	000	0001	110
+0.5	0	000	0000	100
+0.125	0	000	0000	001
-0.125	1	111	1111	111
-1.125	1	111	1110	111
-25.5	1	110	0110	100
-55.25	1	100	1000	110
-65.000	1	011	1111	000



Biwa Thermal Table 1106

Sensor	Type	T6	T7
Sensor 0	CPU DTS	100	102
Sensor 1	CPU G792 Analog	110	113
Sensor 2	System G792	85	87
Sensor 3	T8		
Sensor 4	ADIA status		

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

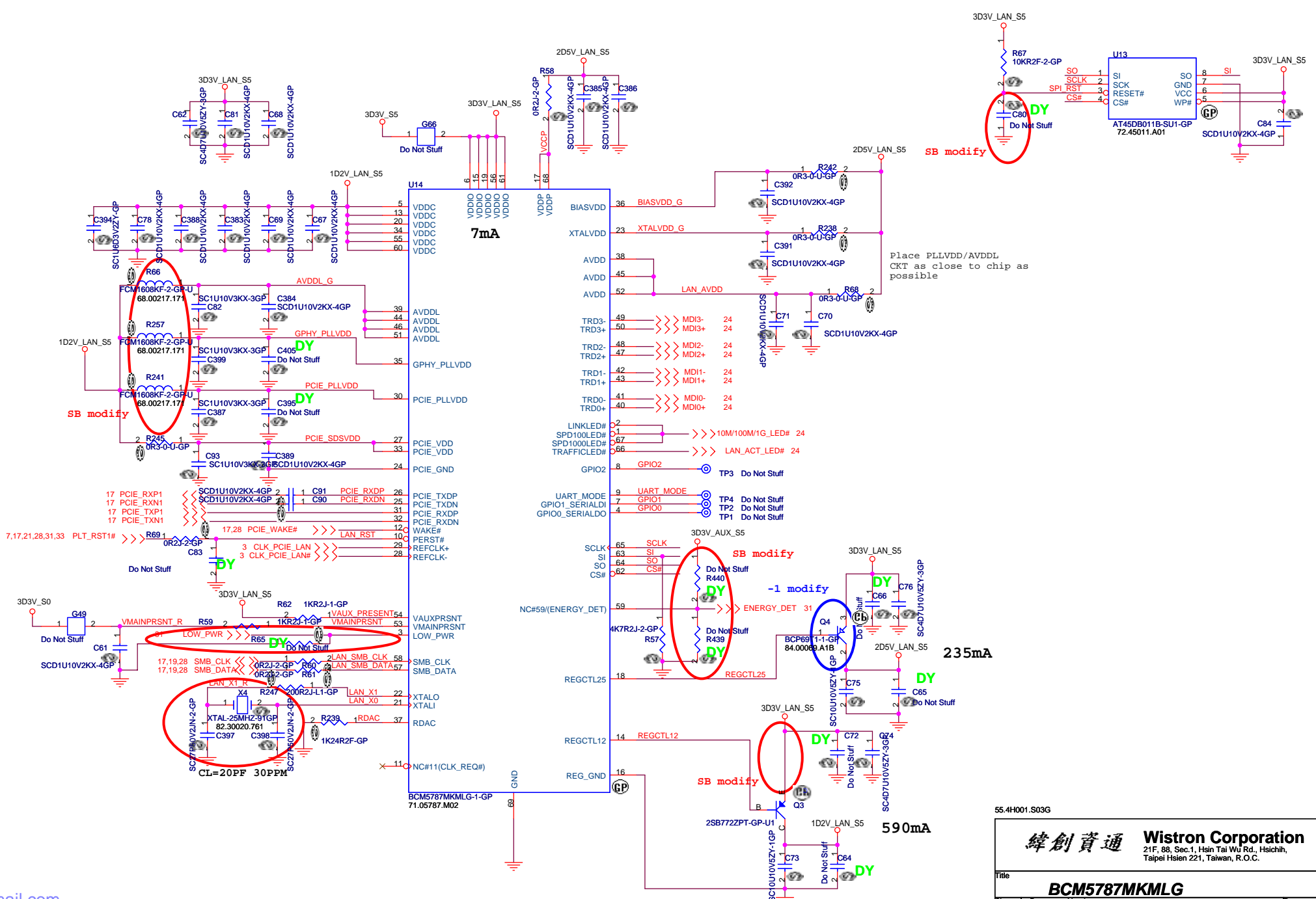
Title: **Thermal/Fan Controller**

Size: Document Number: **Biwa** Rev: **SB**

Date: Thursday, March 01, 2007 Sheet 20 of 42







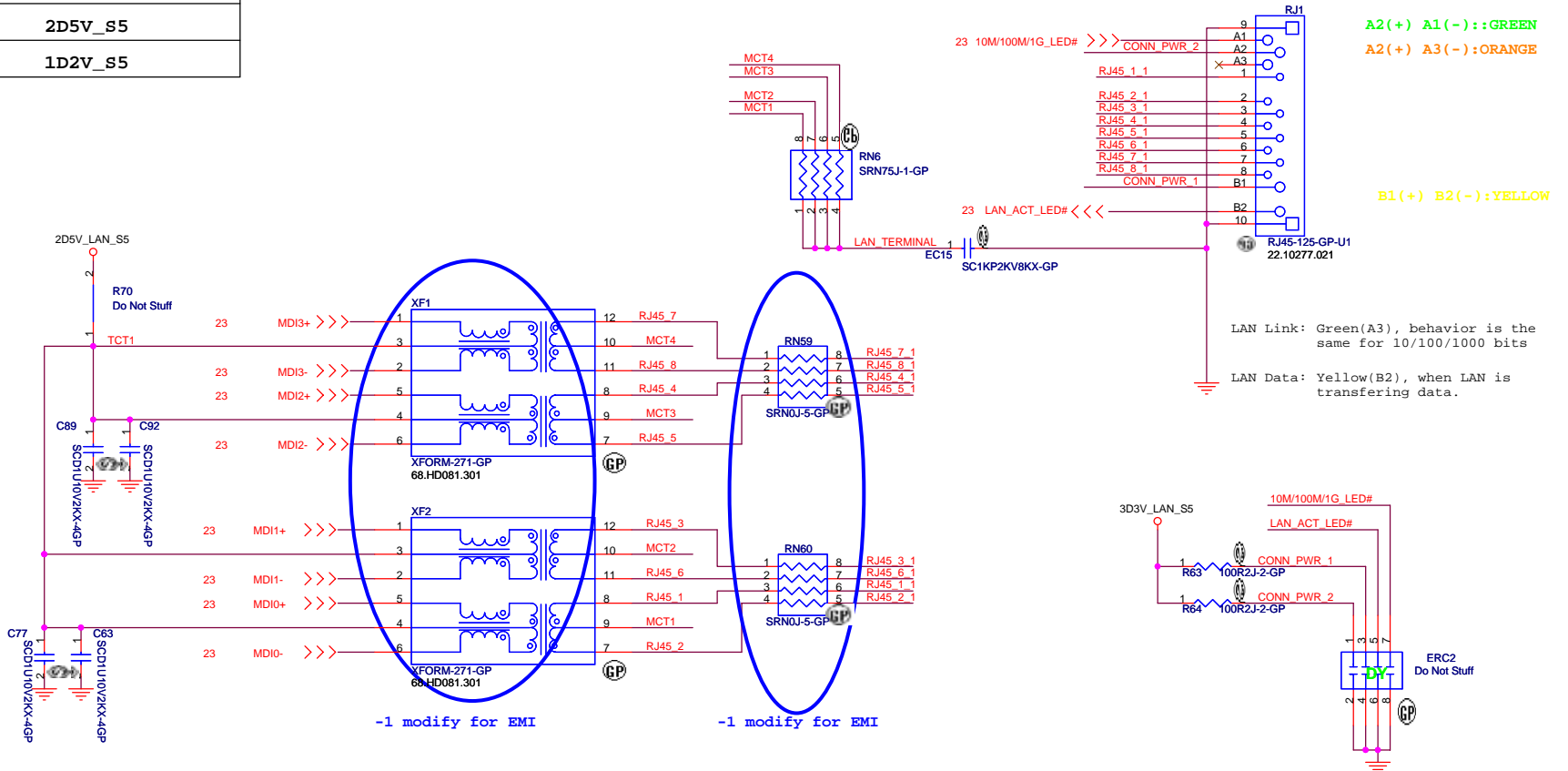
Voltage Rail	4401E	5789	5787
VDDIO_PCI	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDC	1D8V_LAN_S5	1D2V_LAN_S5	
VDDIO	3D3V_LAN_S5	3D3V_LAN_S5	
VESD	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDP	Don't Care	2D5V_S5	
3D3V_2D5V_S5	3D3V_S5	2D5V_S5	
1D8V_1D2V_S5	1D8V_LAN_S5	1D2V_S5	

# LAN Connector

LED COLOR

A2(+) A1(-)::GREEN  
A2(+) A3(-):ORANGE

B1(+) B2(-):YELLOW



LAN Link: Green(A3), behavior is the same for 10/100/1000 bits

LAN Data: Yellow(B2), when LAN is transferring data.

1. route on bottom as differential pairs.
2. Tx+/Tx- are pairs. Rx+/Rx- are pairs.
3. No vias, No 90 degree bends.
4. pairs must be equal lengths.
5. 6mil trace width, 12mil separation.
6. 36mil between pairs and any other trace.
7. Must not cross ground moat, except RJ-45 moat.

RJ11 signal must leave the other signal or power plane 100mil.

DOC\_TIP, DOC\_RING, TIP, RING:  
W/S : 10/100 @ Surface layers  
10/20 @ Inner layers

10/100 LAN Transformer	RJ45 PIN
TD+ --> TX+	RJ45-1
TD- --> TX-	RJ45-2
RD+ --> RX+	RJ45-3
RD- --> RX-	RJ45-6

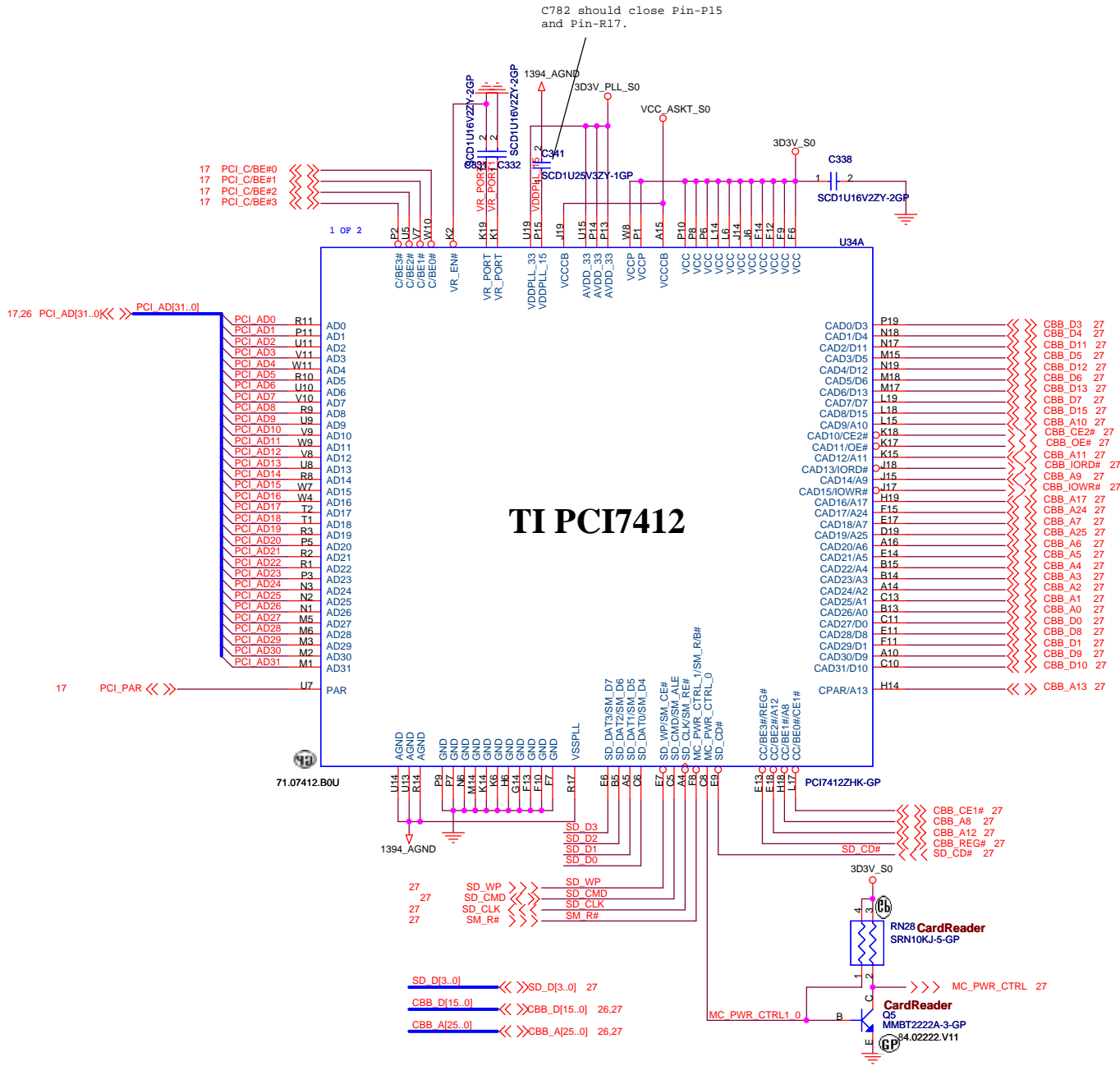
55.4H001.S03G

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title <b>LAN Connector</b>		
Size A3	Document Number <b>Biwa</b>	Rev <b>-1</b>
Date: Thursday, March 01, 2007	Sheet 24 of 42	

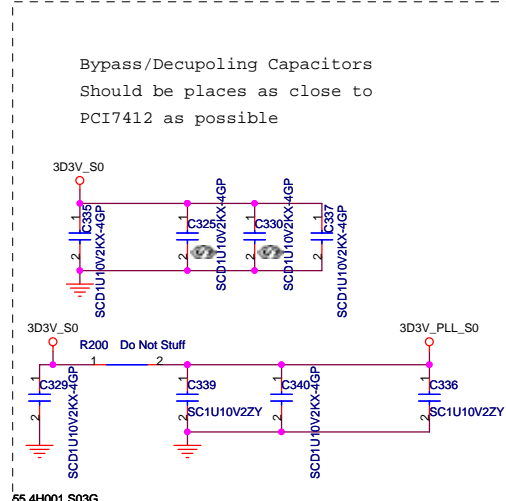


C782 should close Pin-P15 and Pin-R17.



• All 1394 signals must be routed on top side only  
 • Differential pairs of each ports should have equal trace length  
 • Stubs must be keep as short as possible

# TI PCI7412



55.4H001.S03G

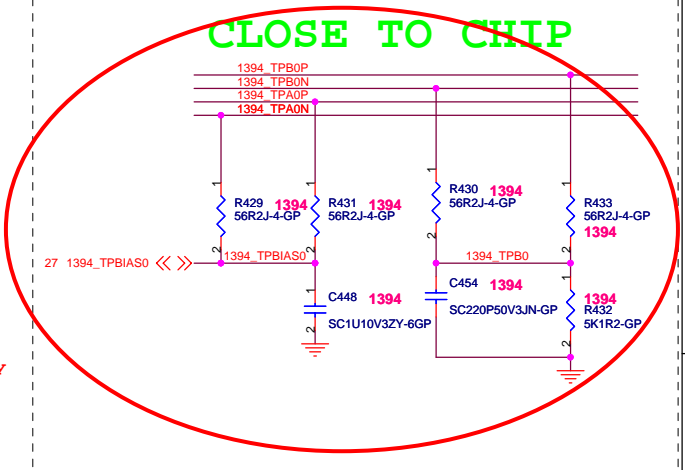
**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **TI PCI7412 (1 of 2)**

Size: Document Number Rev: SA

Date: Thursday, March 01, 2007 Sheet 25 of 42

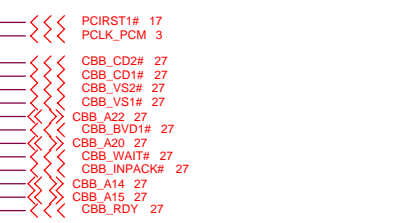
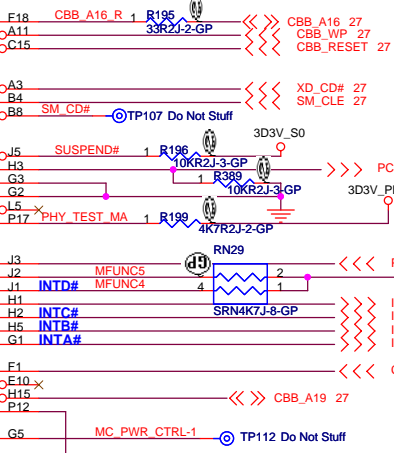
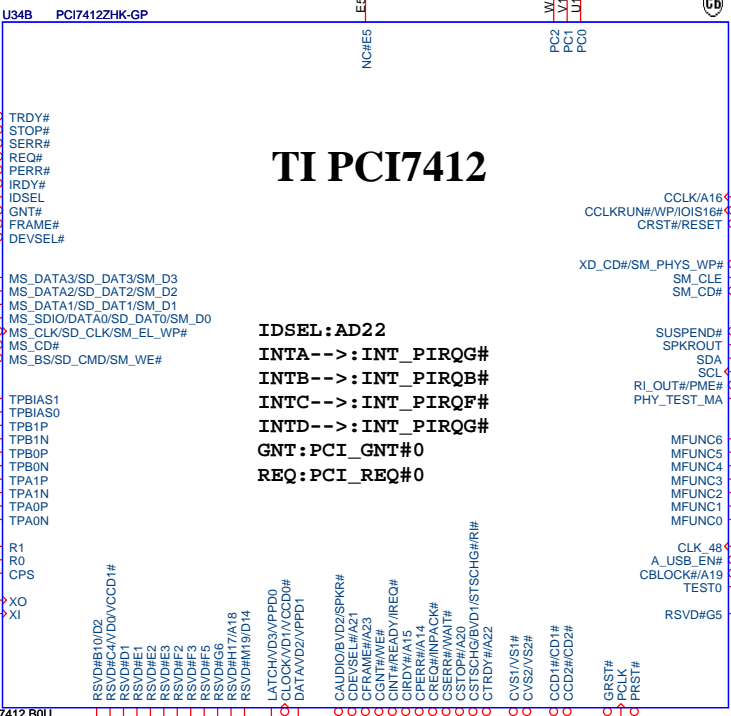
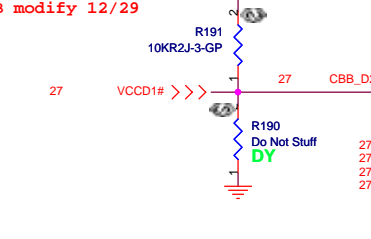
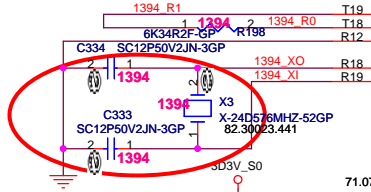
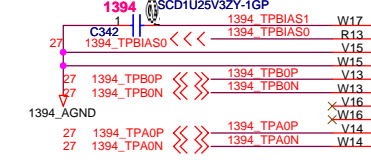
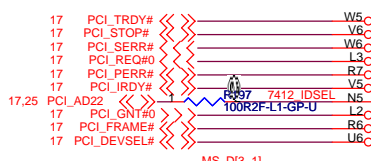
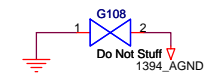
CLOSE TO CHIP



SB modify

# TI PCI7412

**IDSEL:AD22**  
**INTA---:INT\_PIRQG#**  
**INTB---:INT\_PIRQB#**  
**INTC---:INT\_PIRQF#**  
**INTD---:INT\_PIRQG#**  
**GNT:PCI\_GNT#0**  
**REQ:PCI\_REQ#0**



INTA# CARBUS 1 (INT\_PIRQG#)  
INTB# 1394 (INT\_PIRQB#)  
INTC# Flash Media (INT\_PIRQF#)  
INTD# SD Host (INT\_PIRQG#) share  
MFUNC4: use bit 19-16 Register define.

55.4H001.S03G

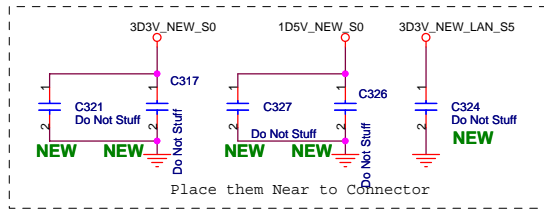
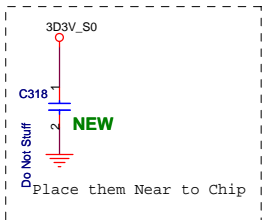
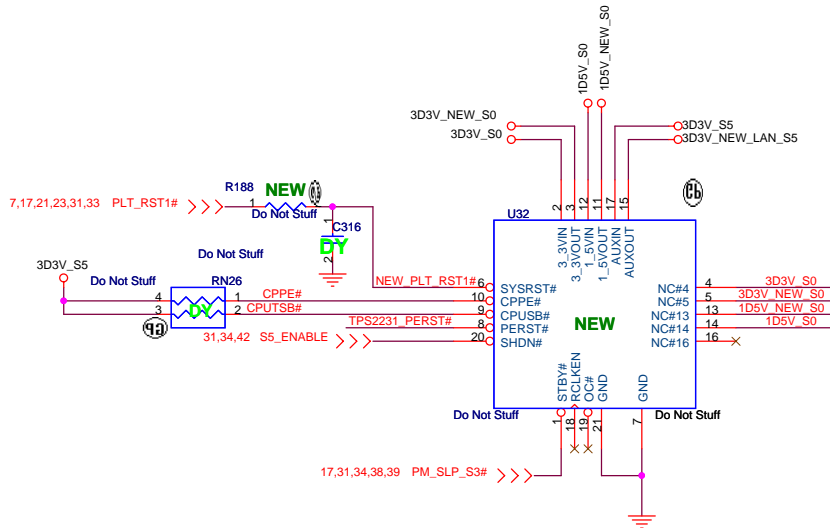
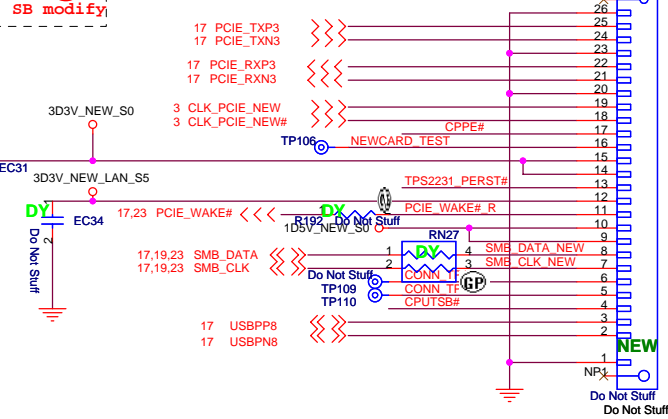
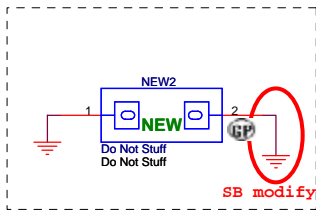
緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title		TI PCI7412 (2 of 2)	
Size	Document Number	Rev	SB
Date	Thursday, March 01, 2007	Sheet	26 of 42

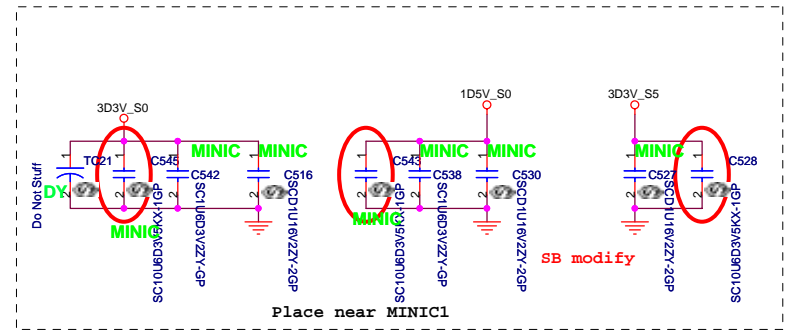
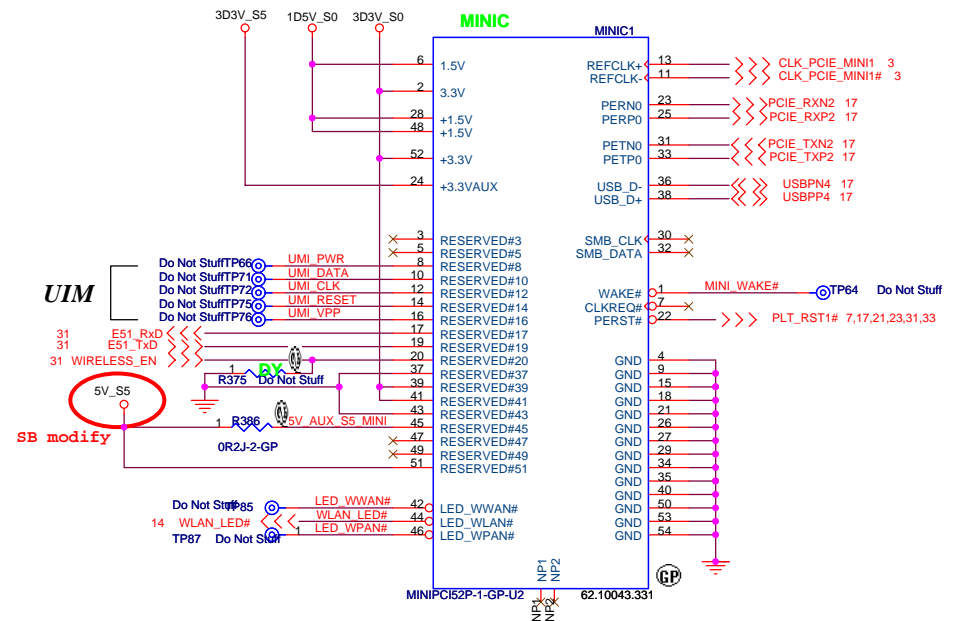


# NEWCARD Connector

Reserve the symbol for bottom side connector



# Mini Card Connector



55.4H001.S03G

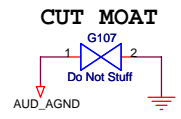
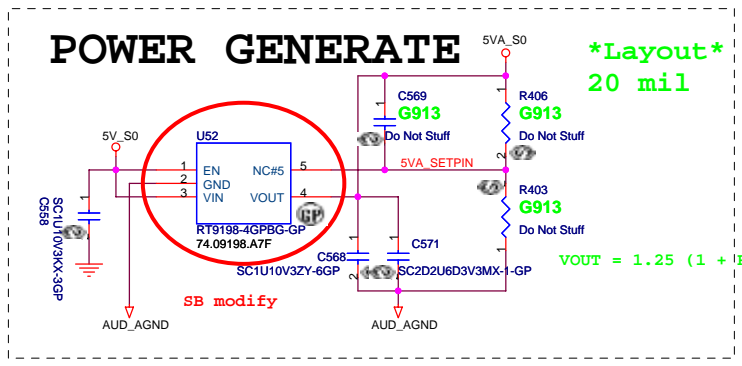
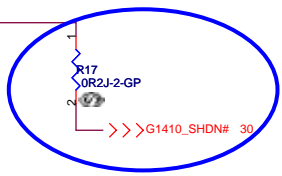
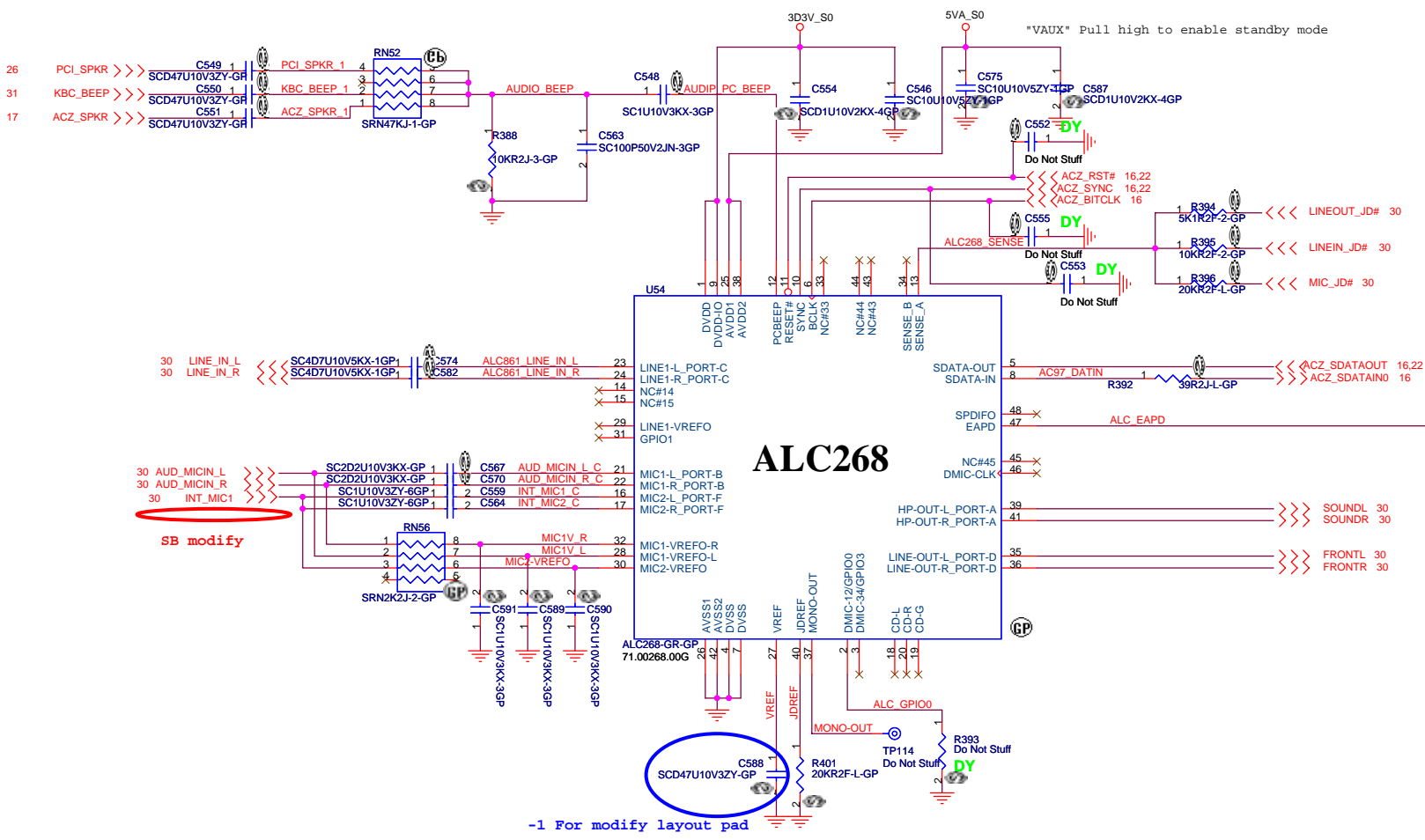
**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **MINI CARD / NEW CARD**

Size: Document Number Rev

Date: Thursday, March 01, 2007 Sheet 28 of 42

**Biwa** **SB**



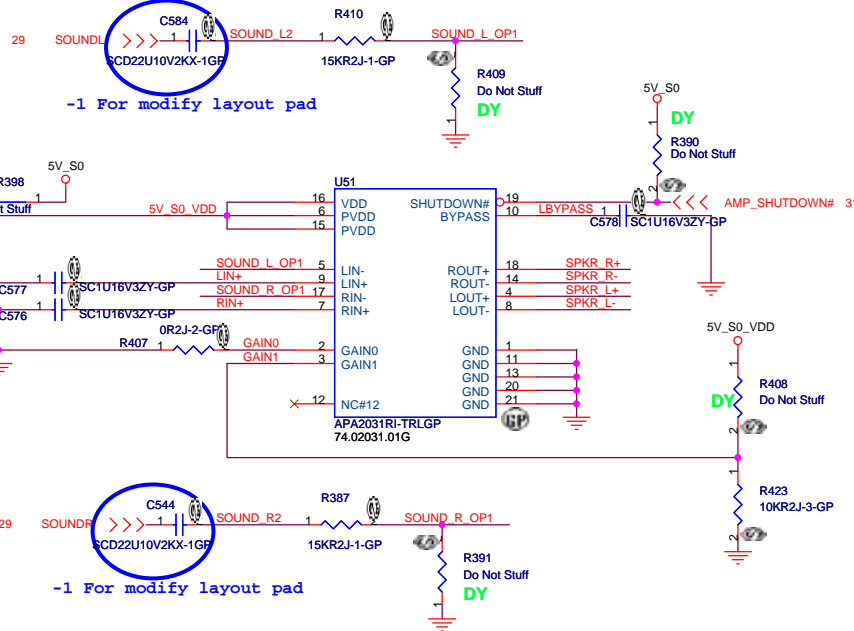
55.4H001.S03G

緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title		AZALIA CODEC - ALC268	
Size	Document Number	Biwa	Rev
			-1
Date:	Thursday, March 01, 2007	Sheet	29 of 42

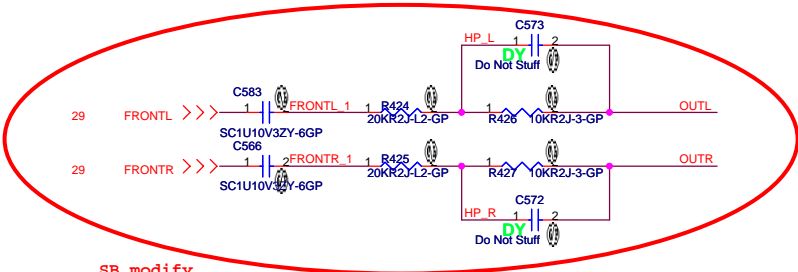
# AUDIO OP AMPLIFIER

I/P signal level  
need +5V level

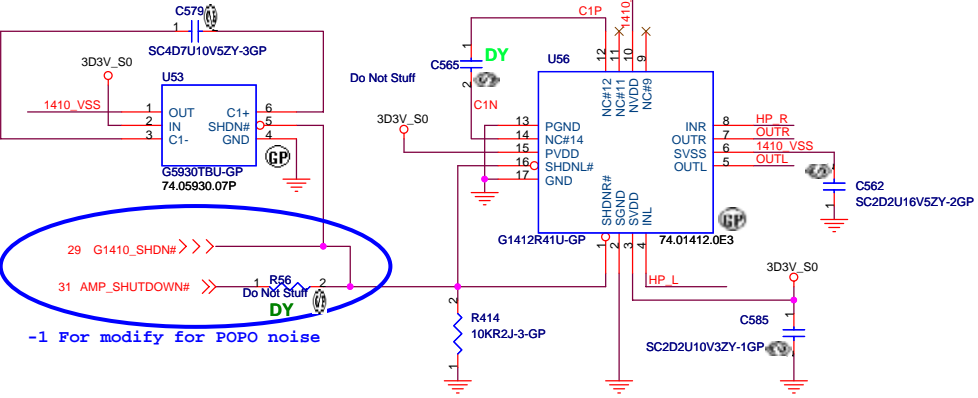


-1 For modify layout pad

-1 For modify layout pad

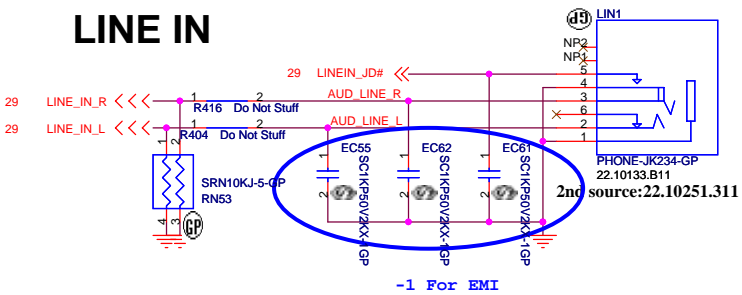


SB modify



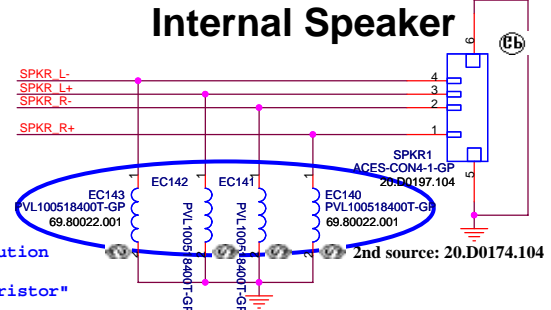
-1 For modify for POPO noise

## LINE IN



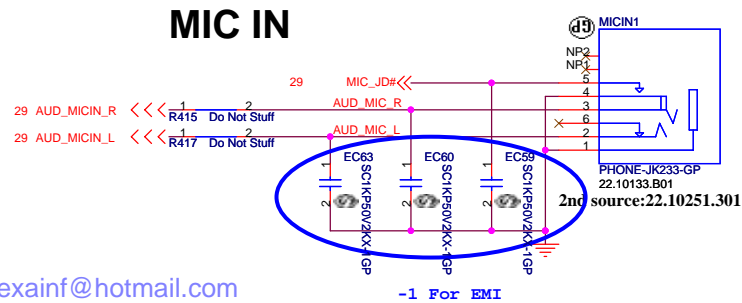
-1 For EMI

## Internal Speaker



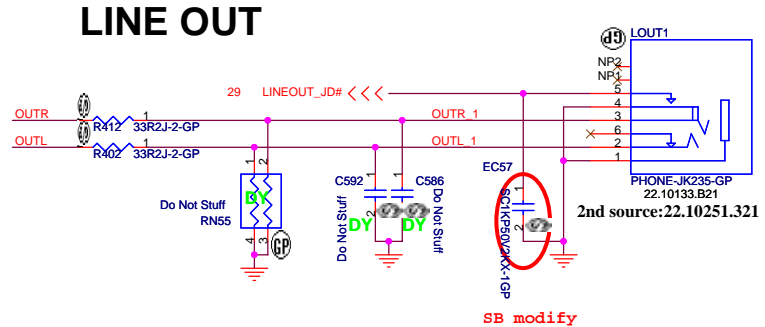
-1 For modify for ESD solution  
Close to SPKR1  
Reserved 0402 pad for "Varistor"

## MIC IN



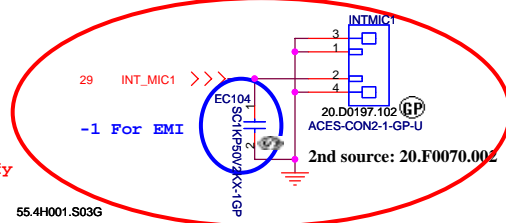
-1 For EMI

## LINE OUT



SB modify

## Internal Microphone



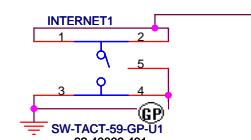
SB modify

緯創資通 Wistron Corporation  
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

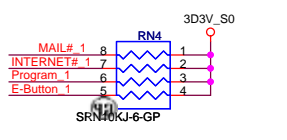
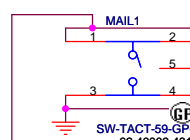
Title		AUDIO AMP AND JACK	
Size	Document Number	Rev	
A3		-2	
Date:	Thursday, March 01, 2007	Sheet	30 of 42



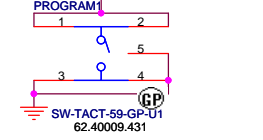
### Internet Button



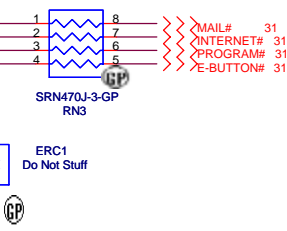
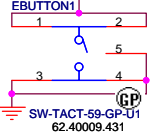
### Mail Button



### Program Button

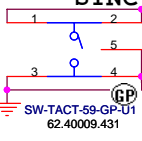


### E-Button

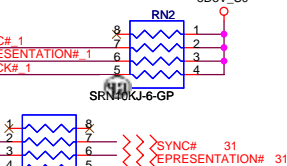
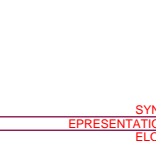


2nd source: 62.40009.561

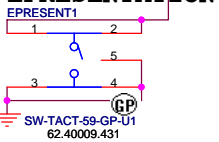
### SYNC



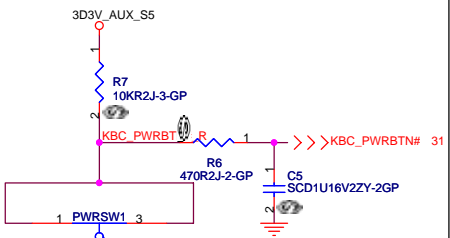
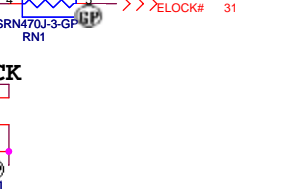
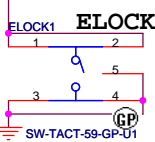
### E-Representation



### E-Representation

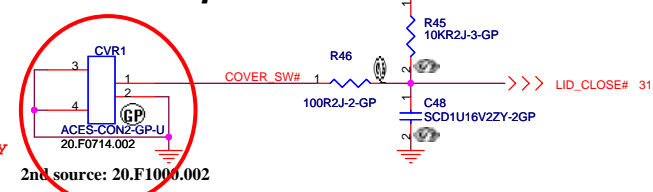


### E-Block



### Power Button

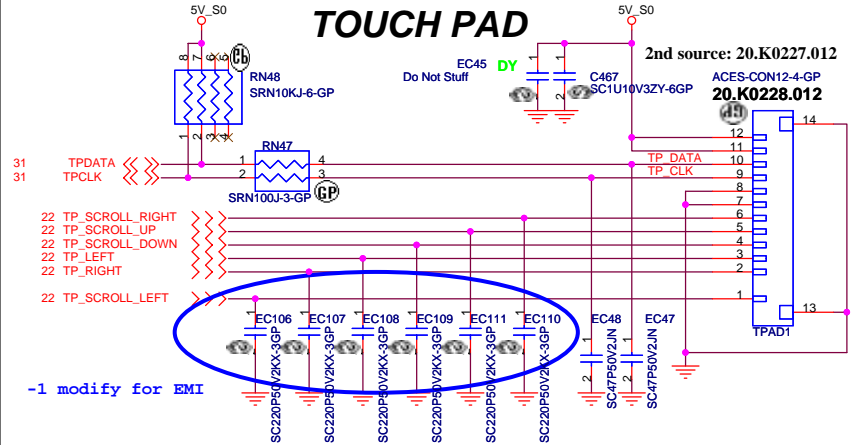
### Cover Up Switch



SB modify

2nd source: 20.F1000.002

### TOUCH PAD



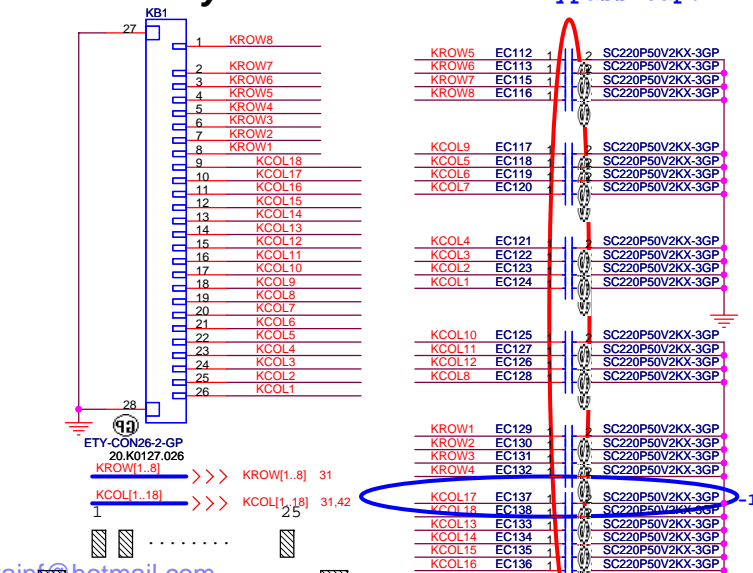
2nd source: 20.K0227.012

20.K0228.012

-1 modify for EMI

### Internal KeyBoard CONN

EMI Bypass cap.

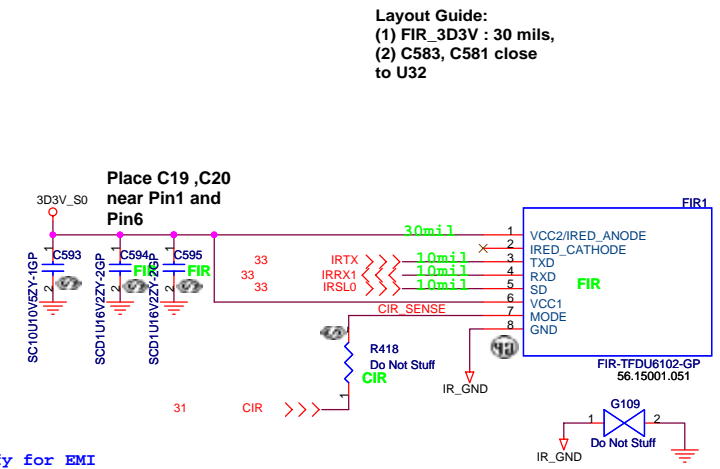


1 modify for EMI

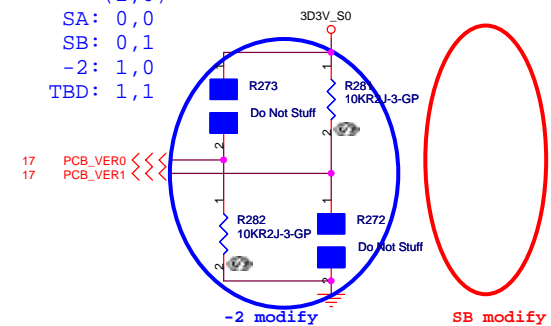
SB modify For EMI

### VISHAY FIR Module

Layout Guide:  
 (1) FIR\_3D3V : 30 mils,  
 (2) C583, C581 close to U32



PlanarID  
 (1,0)  
 SA: 0,0  
 SB: 0,1  
 -2: 1,0  
 TBD: 1,1



-2 modify

SB modify

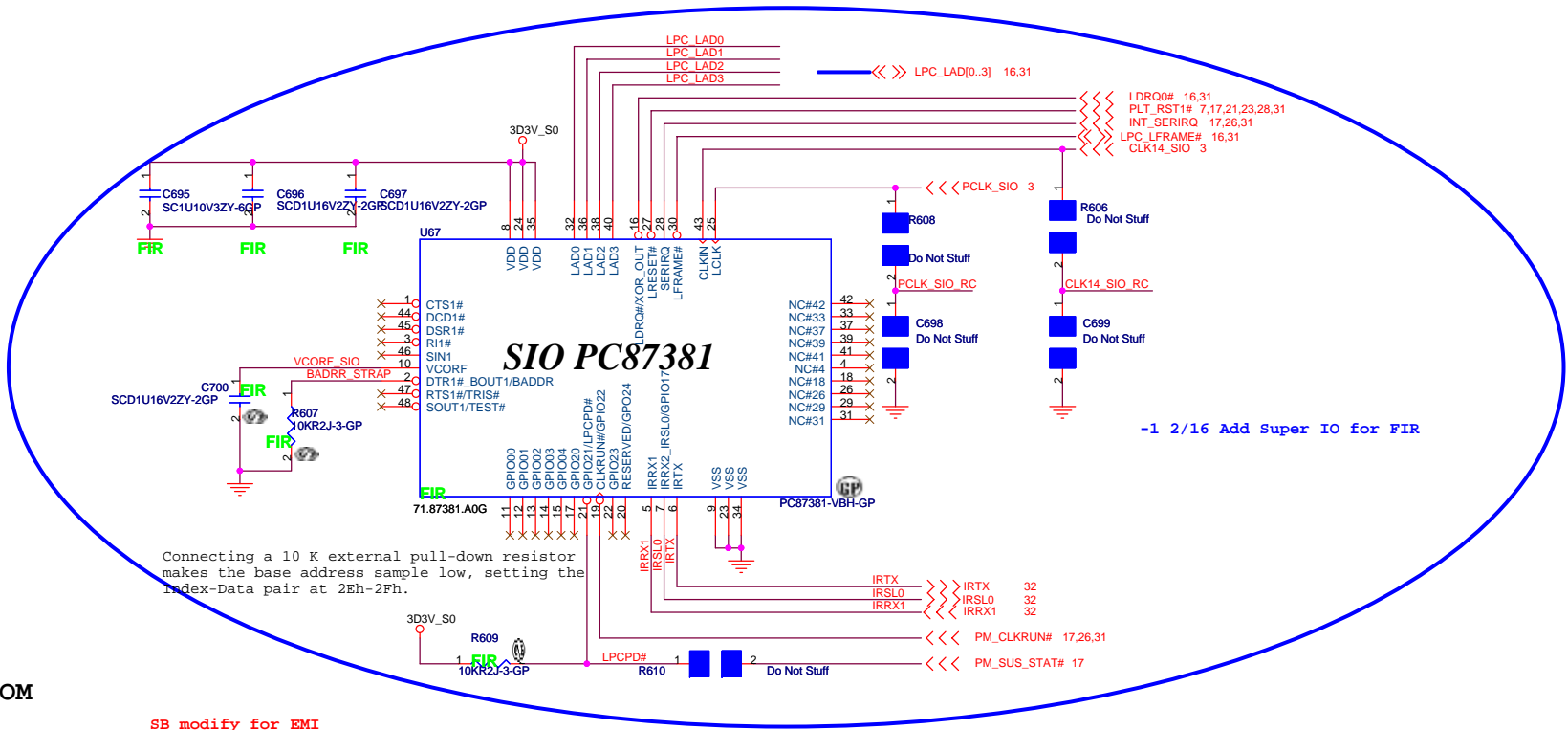
55.4H001.S03G

緯創資通 Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

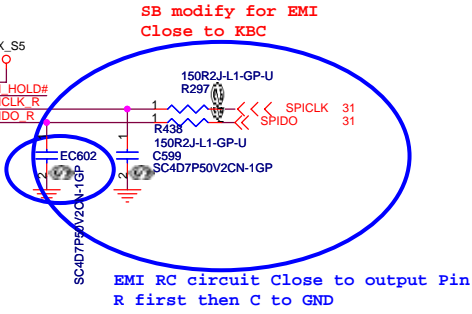
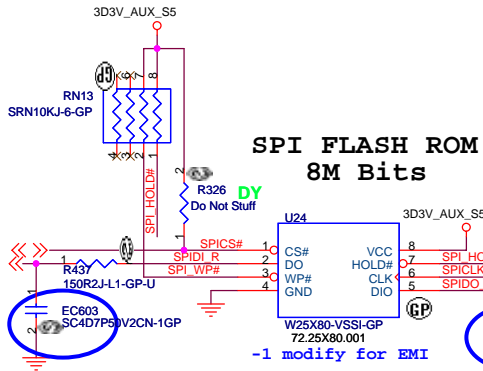
Title	BUTTONs / KB / TOUCHPAD / FIR		
Size	Document Number		Rev
			-2
Date:	Thursday, March 01, 2007	Sheet	32 of 42

hexainfo@hotmail.com  
 GRATIS FOR FREE  
 CHECK KB SPEC AND PIN DEFINE





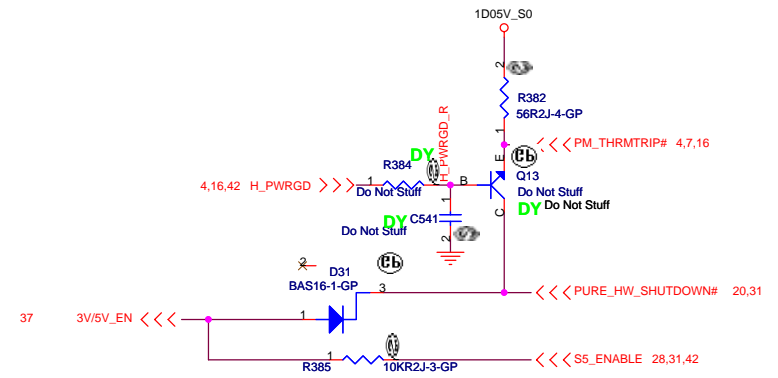
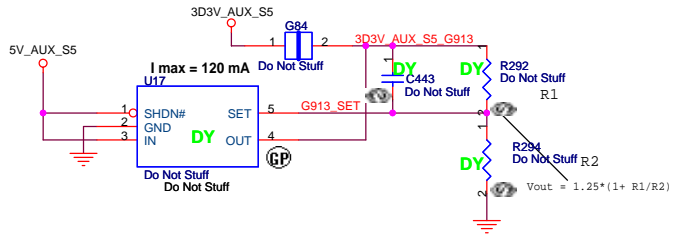
Connecting a 10 K external pull-down resistor makes the base address sample low, setting the Index-Data pair at 2Eh-2Fh.



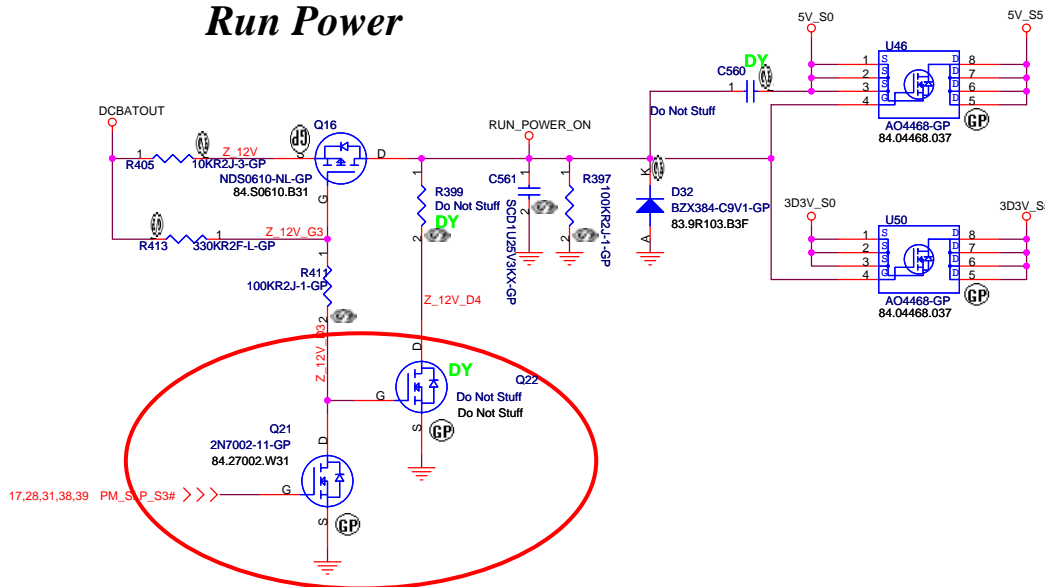
55.4H001.S03G

<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>BIOS &amp; Super IO</b>			
Size A3	Document Number	Rev -2	
	<b>Biwa</b>		
Date: Thursday, March 01, 2007	Sheet 33	of	42

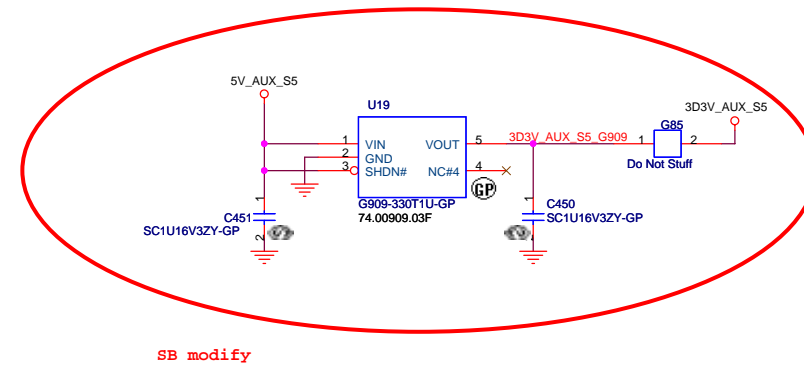
## Aux Power 3D3V\_AUX\_S5



## Run Power



## Aux Power 3D3V\_AUX\_S5



55.4H001.S03G

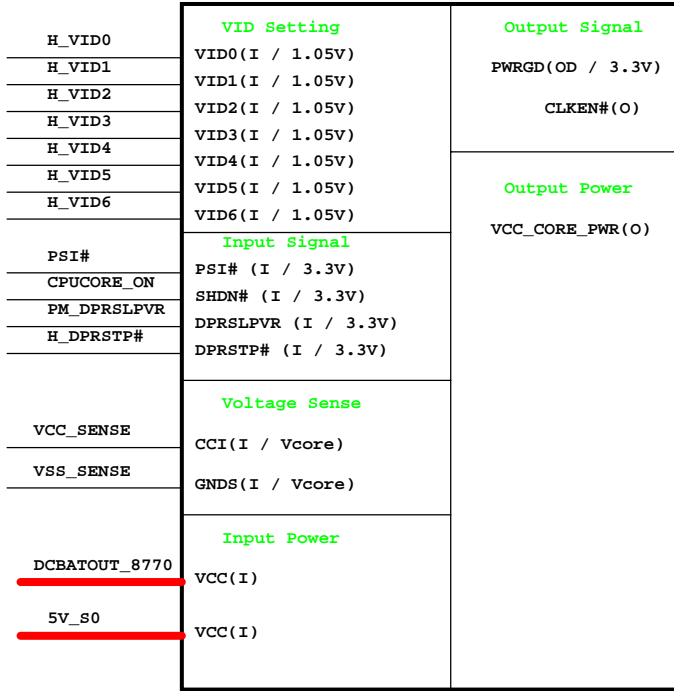
緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title **RUN POWER and 3D3V\_AUX\_S5**

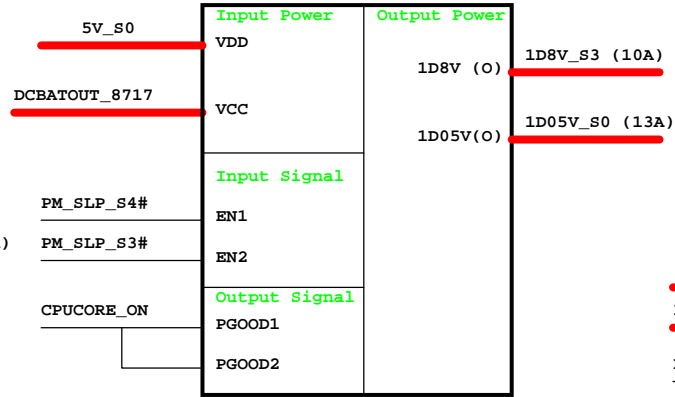
Size Document Number **Biwa** Rev **-1**

Date: Thursday, March 01, 2007 Sheet 34 of 42

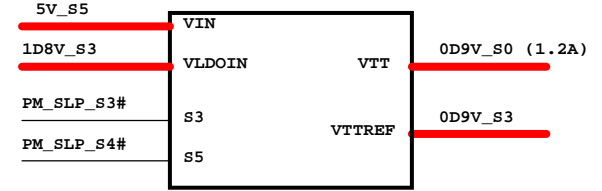
**CPU\_CORE**  
**MAXIM MAX8770**



**MAX8717**  
**1D8V/1D05V**

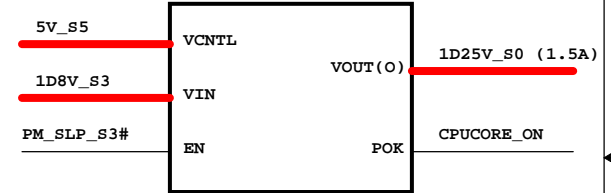


**0D9V\_S0**



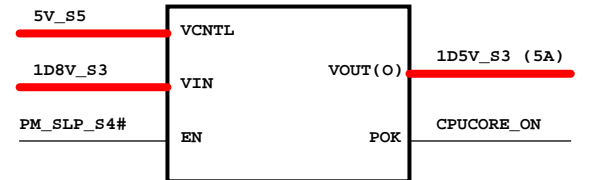
**TPS51100**

**1D25V\_S0**



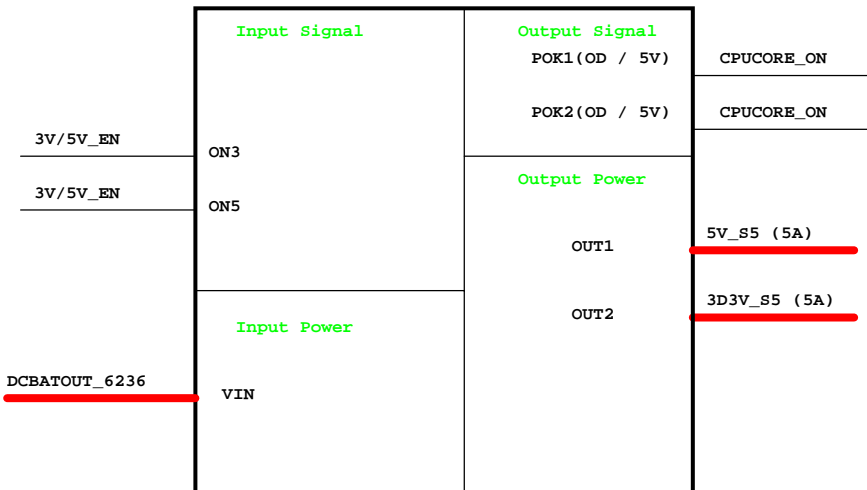
**APL5915**

**1D5V\_S3**

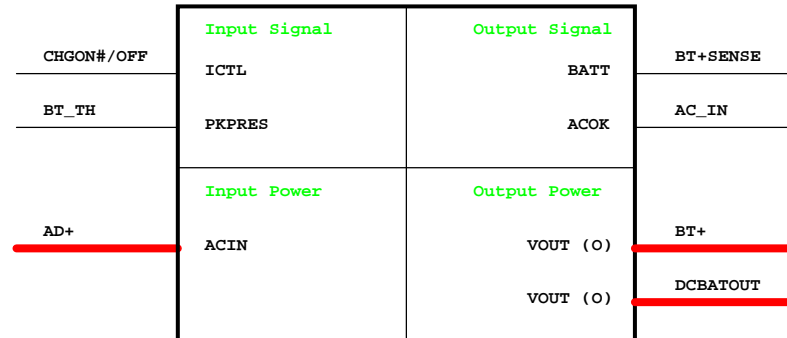


**APL5912**

**ISL6236**  
**5V/3D3V**



**Charger ISL6255**



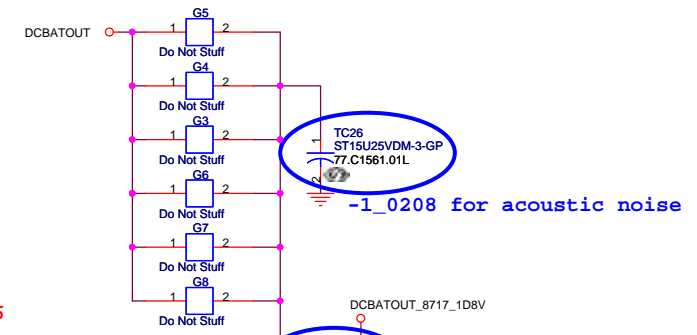
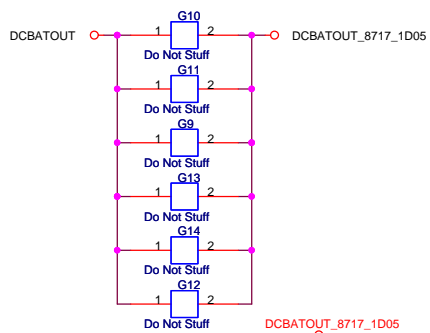
55.4H001.S03G

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title		
<b>Power Block Diagram</b>		
Size	Document Number	Rev
A3		SA
Date:	Thursday, March 01, 2007	Sheet 35 of 42

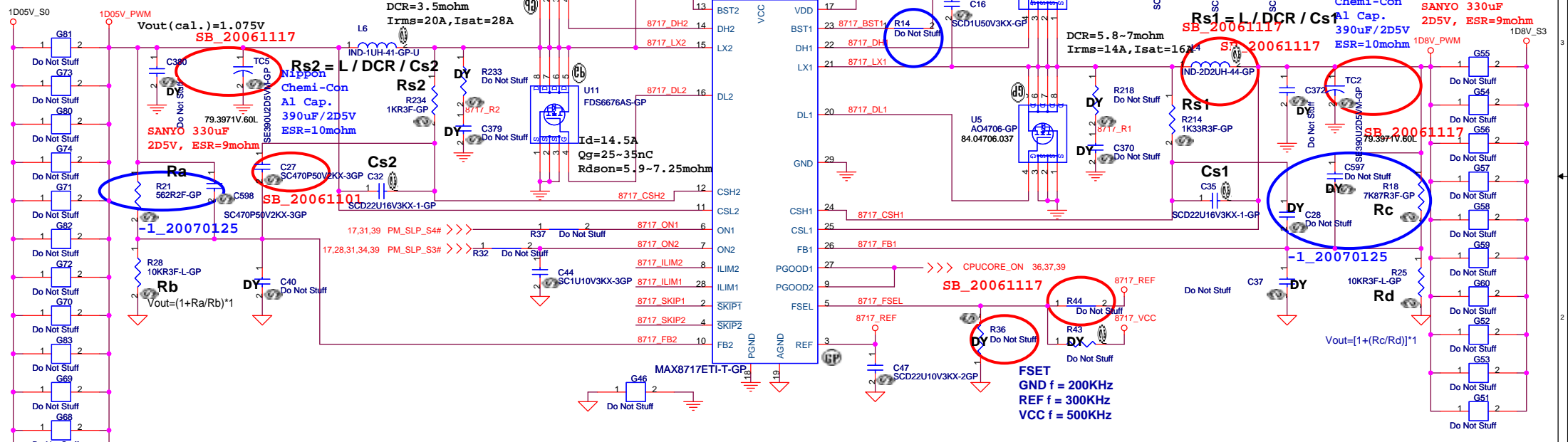




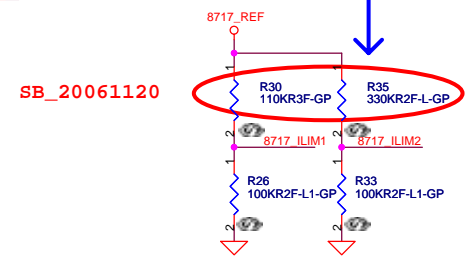


**I<sub>omax</sub>=13A**  
**OCP>18.6A(20V),17A(9V)**

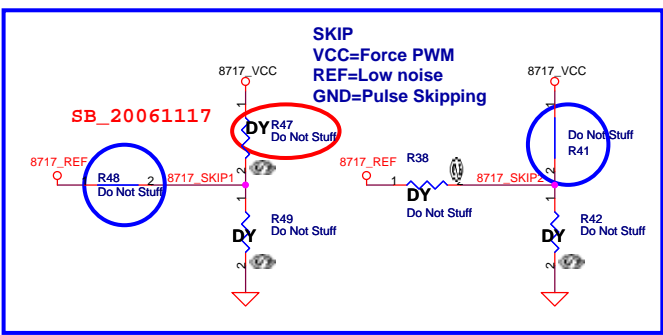
**I<sub>omax</sub>=10A**  
**OCP>14.8A(20V),14.2A(9V)**  
**Nippon Chemi-Con SANYO 330uF**  
**Al Cap. 2D5V, ESR=9mohm**  
**V<sub>out</sub>(cal.)=1.845V**



Adjust the current limit threshold from R30, R35

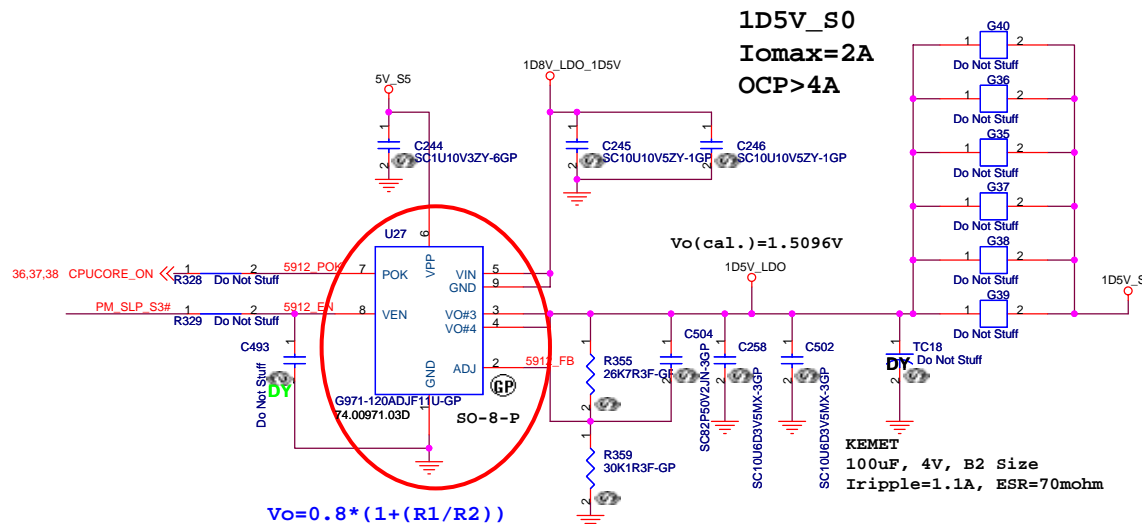
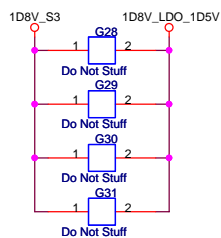
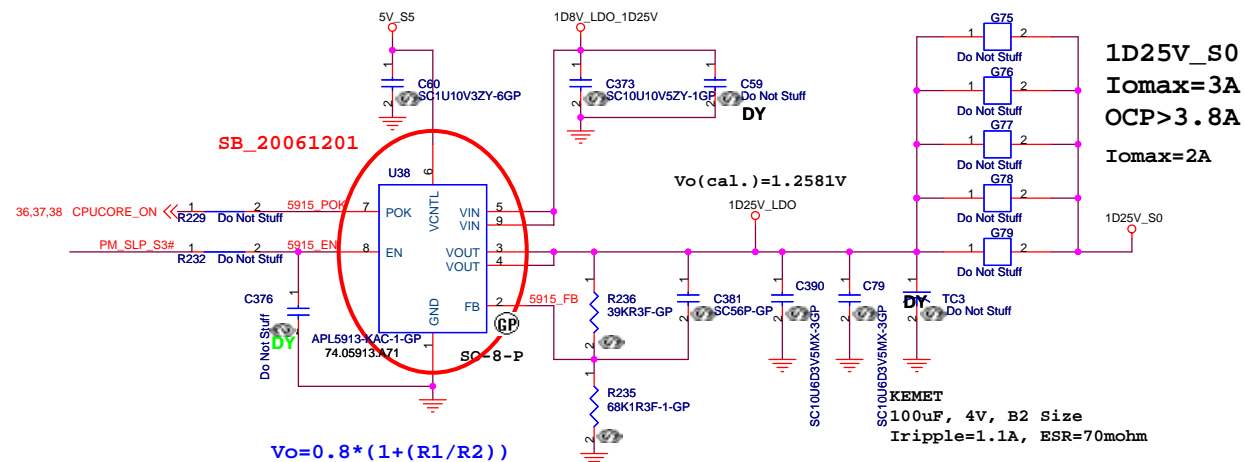
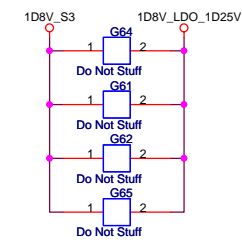
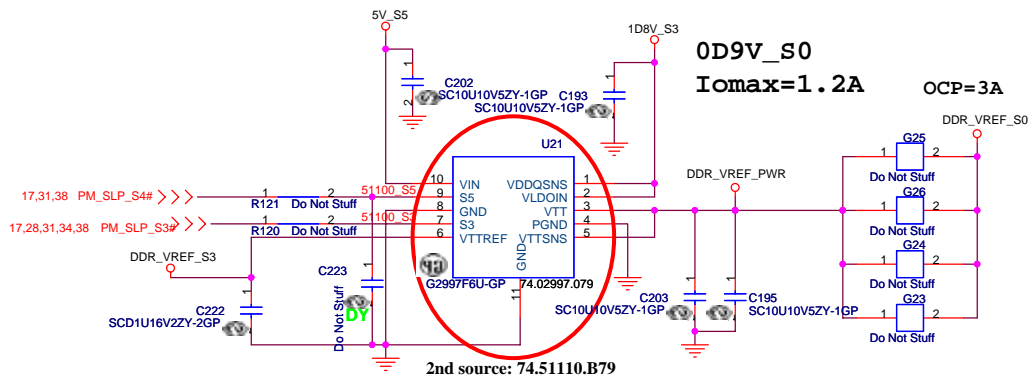


VILIM = 0.5V~2.0V  
 Output Current = ILIM / 10 / LDCR - di/2



**SKIP**  
**VCC=Force PWM**  
**REF=Low noise**  
**GND= Pulse Skipping**

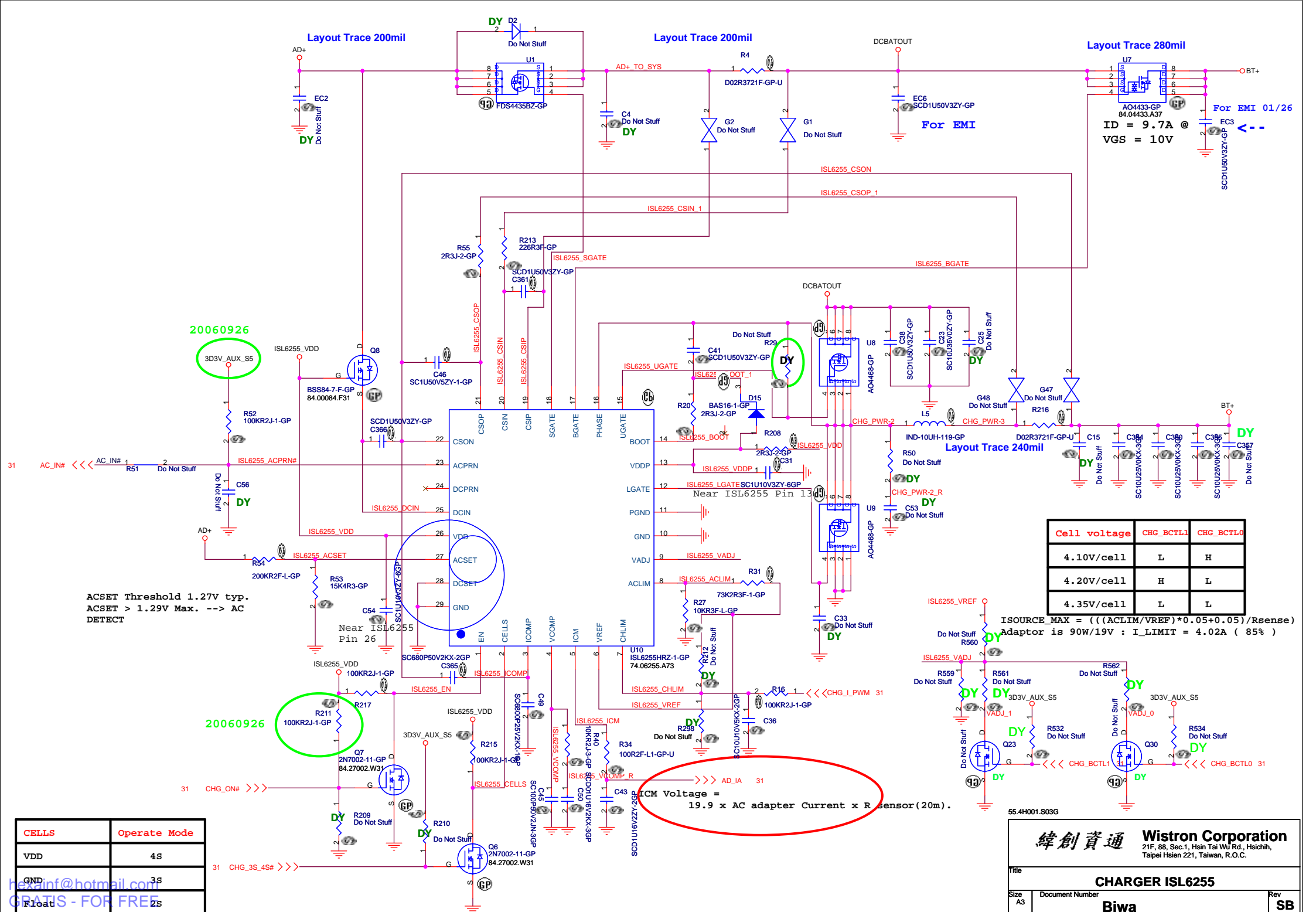
**FSET**  
**GND f = 200KHz**  
**REF f = 300KHz**  
**VCC f = 500KHz**



55.4H001.S03G

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title		<b>1D25V/1D5V/0D9V</b>	
Size	Document Number	Rev	
A3	<b>Biwa</b>	<b>SB</b>	
Date:	Thursday, March 01, 2007	Sheet	39 of 42



Layout Trace 200mil

Layout Trace 200mil

Layout Trace 280mil

For EMI

For EMI 01/26  
ID = 9.7A @  
VGS = 10V

20060926

Layout Trace 240mil

ACSET Threshold 1.27V typ.  
ACSET > 1.29V Max. --> AC  
DETECT

Cell voltage	CHG_BCTL1	CHG_BCTL0
4.10V/cell	L	H
4.20V/cell	H	L
4.35V/cell	L	L

ISOURCE\_MAX = ((ACLIM/VREF)\*0.05+0.05)/Rsense  
Adaptor is 90W/19V : I\_LIMIT = 4.02A ( 85% )

ICM Voltage =  
19.9 x AC adapter Current x R sensor (20m).

CELLS	Operate Mode
VDD	4S
GND	3S
Float	2S

55.4H001.S03G

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

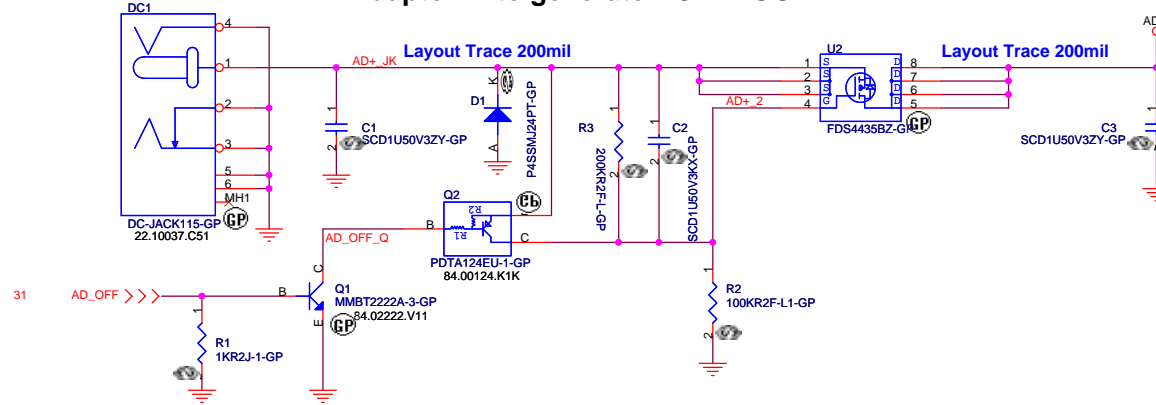
Title: **CHARGER ISL6255**

Size A3 Document Number **Biwa** Rev **SB**

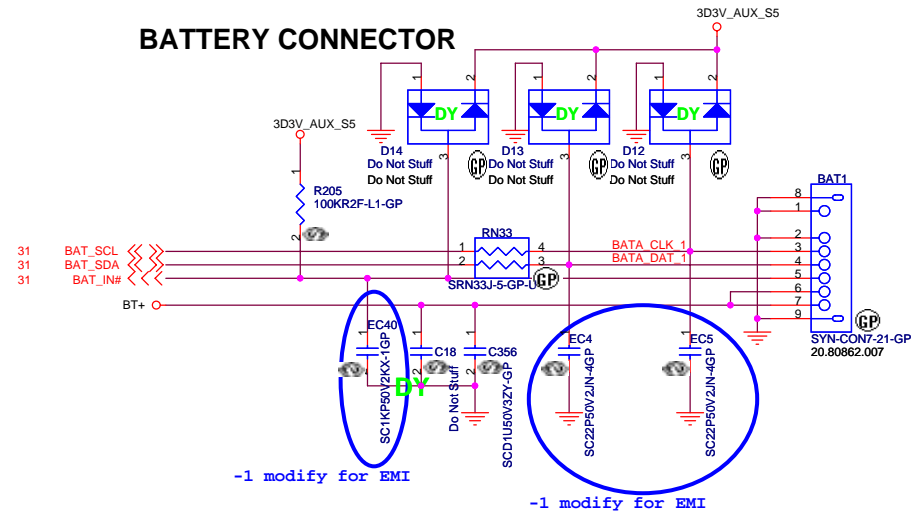
Date: Thursday, March 01, 2007 Sheet 40 of 42



### Adaptor in to generate DCBATOUT



### BATTERY CONNECTOR

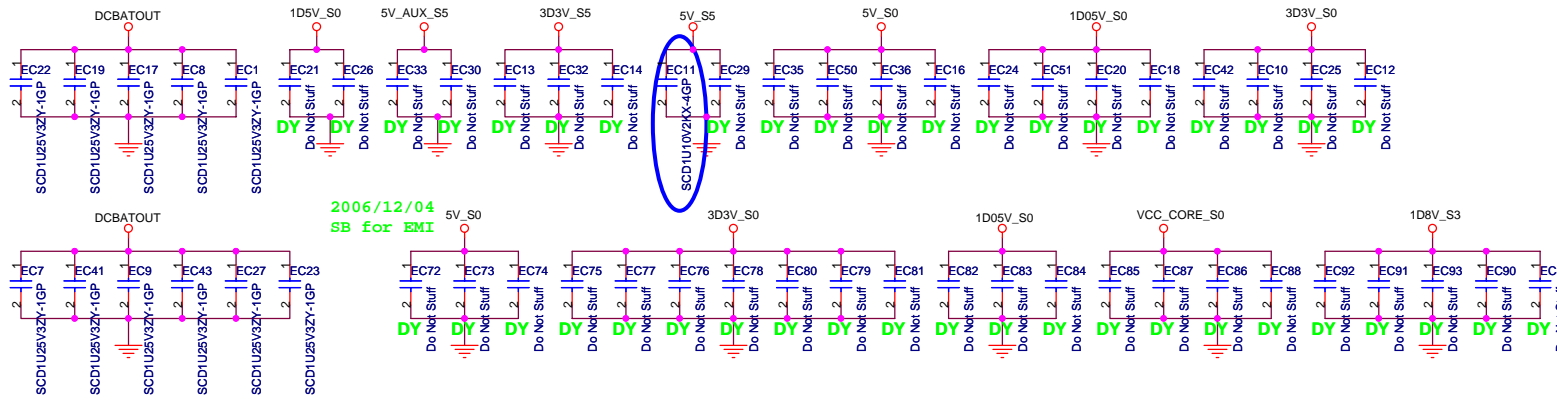


55.4H001.S03G

緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

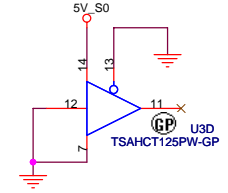
Title <b>AD/BATT CONN</b>		
Size A3	Document Number <b>Biwa</b>	Rev <b>-1</b>
Date: Thursday, March 01, 2007	Sheet 41 of 42	

# EMI Capacitor



2006/12/04  
SB for EMI

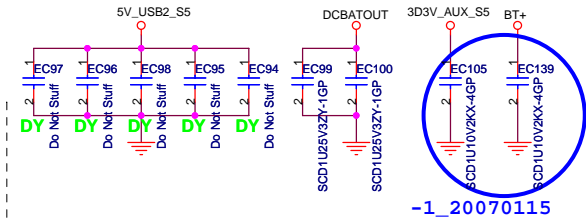
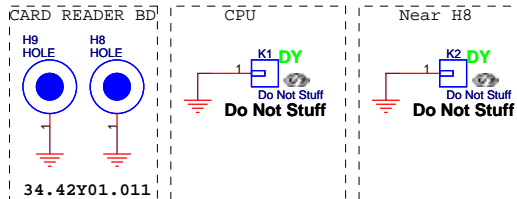
# Unused gate



# KBC JTAG Test Pad

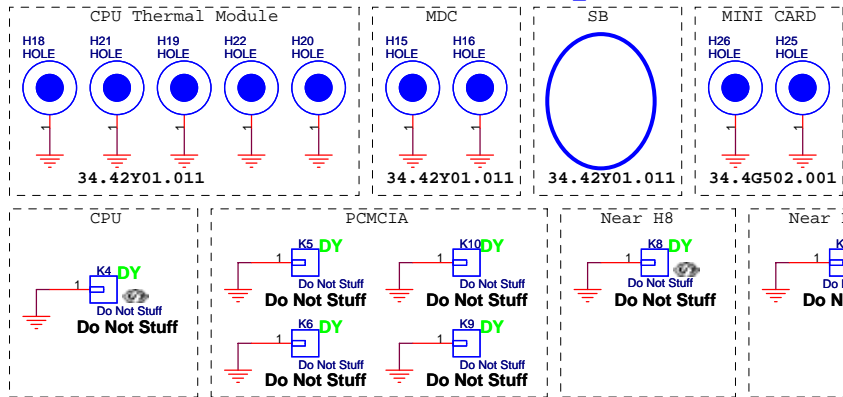
- 31.32 KCOL1 <<< KCOL1 TP88 Do Not Stuff
- 31.32 KCOL2 <<< KCOL2 TP91 Do Not Stuff
- 31.32 KCOL3 <<< KCOL3 TP92 Do Not Stuff
- 31.32 KCOL4 <<< KCOL4 TP90 Do Not Stuff
- 31.32 KCOL6 <<< KCOL6 TP89 Do Not Stuff
- 31.32 KCOL7 <<< KCOL7 TP93 Do Not Stuff

TOP

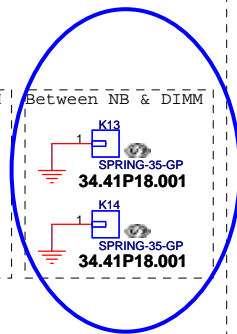


-1\_20070115

BOTTOM



-1\_0131 for thermal

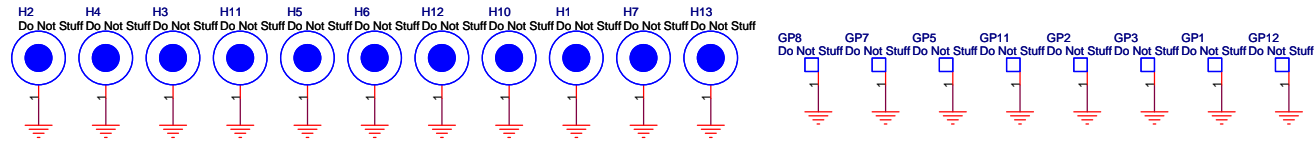


-1\_20070206

# DFX Test Point

- 3D3V\_AUX\_S5 TP97 Do Not Stuff
- 3D3V\_S5 TP102 Do Not Stuff
- 5V\_S5 TP100 Do Not Stuff
- 4,16,34 H\_PWRGD TP31 Do Not Stuff
- 28,31,34 S5\_ENABLE TP86 Do Not Stuff
- 4,6 H\_CPURST# TP39 Do Not Stuff

Test Point放在Dimm Door打開可量測處



55.4H001.S03G

**緯創資通** Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **EMI/Spring/Boss**

Size: Document Number: **Biwa** Rev: **-1**

Date: Thursday, March 01, 2007 Sheet 42 of 42